

Ferromagnetic integrated inductor/noise suppressor

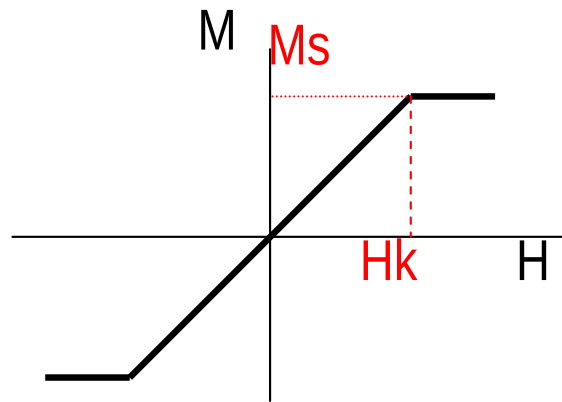
Masahiro YAMAGUCHI

**Department of Electrical and Communication Engineering
Tohoku University**

OUTLINE

1. Thin film permeameter for material evaluation
2. Slit works on thin film inductor
3. Thin film electromagnetic noise suppressor
4. Side channel attack protection
5. Summary

Permeability vs Ferromagnetic Resonance Freq.

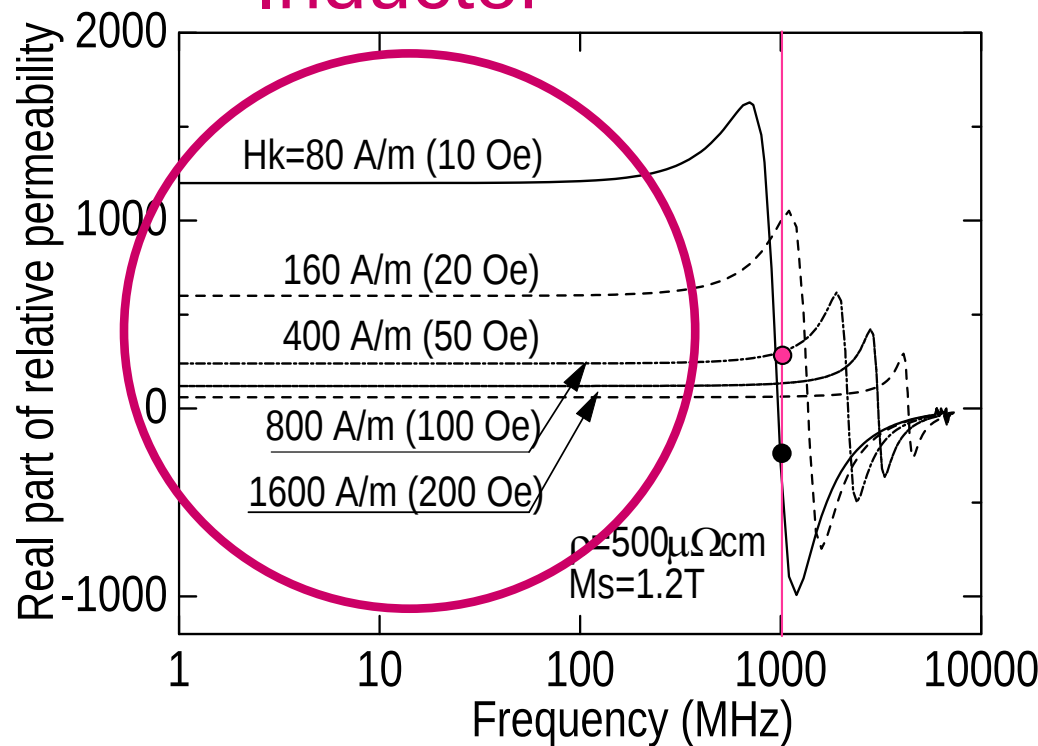


$$\mu = M_s / H_k$$

$$f_r = \frac{\gamma}{2\pi} \sqrt{M_s H_k / \mu_0}$$

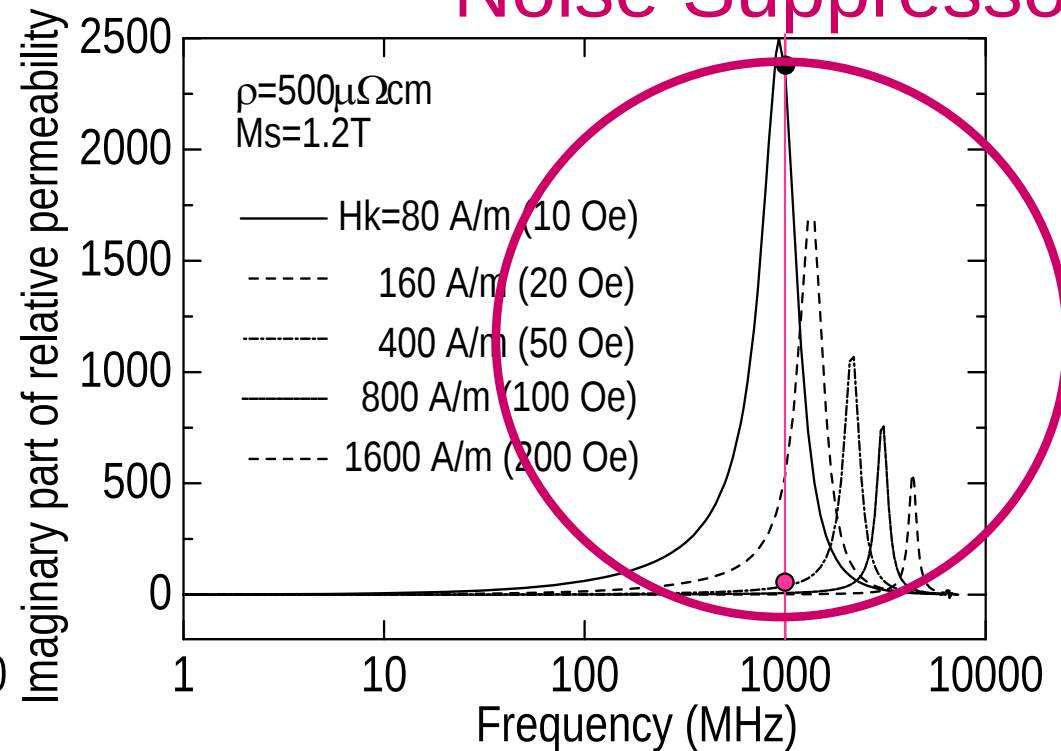
$$\mu \cdot f_r^2 = \text{const}$$

Inductor



(a) Real part

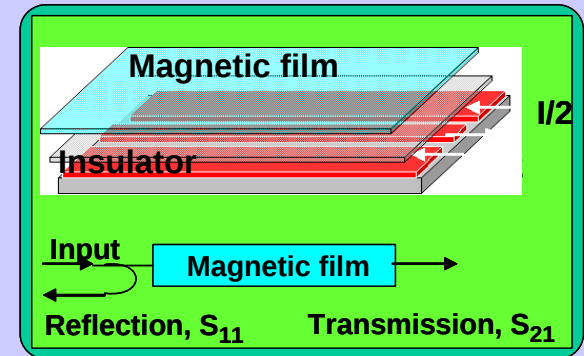
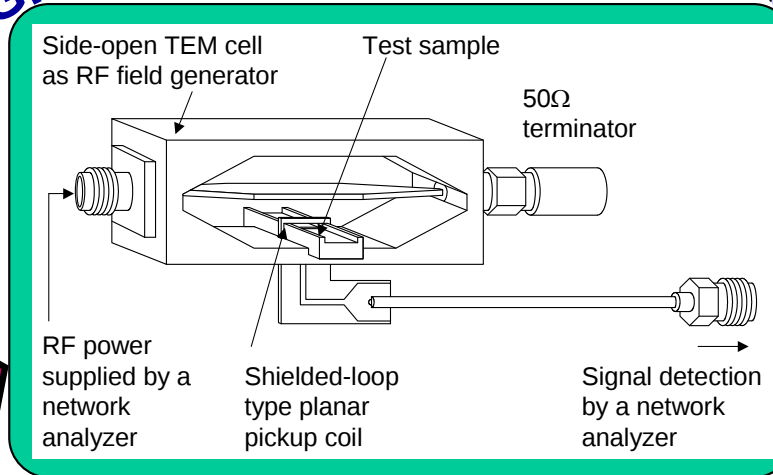
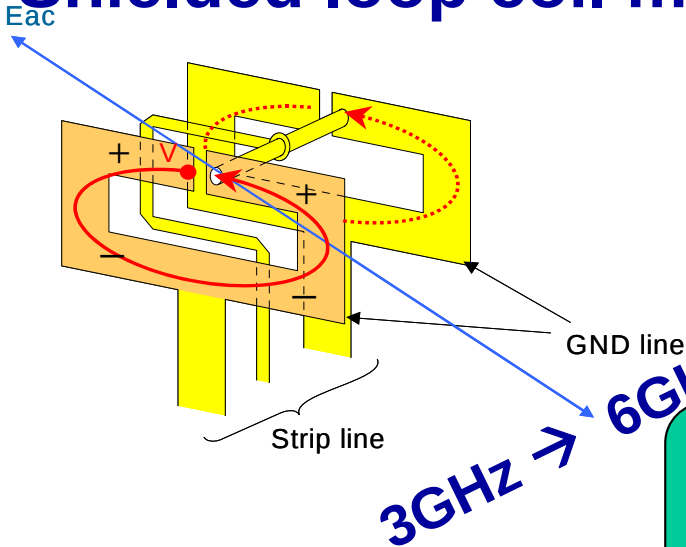
Noise Suppressor



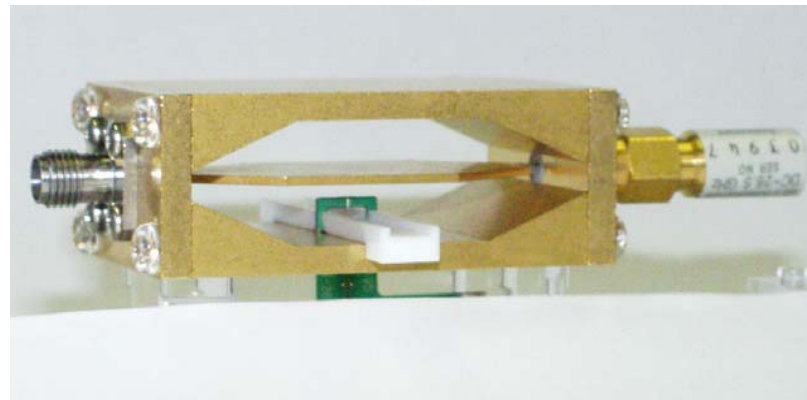
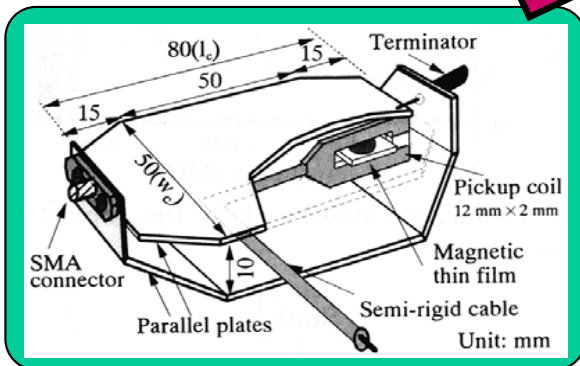
(b) Imaginary part

Development of thin-film permeameter

Shielded loop coil method



**Coplanar line method
(coming)**



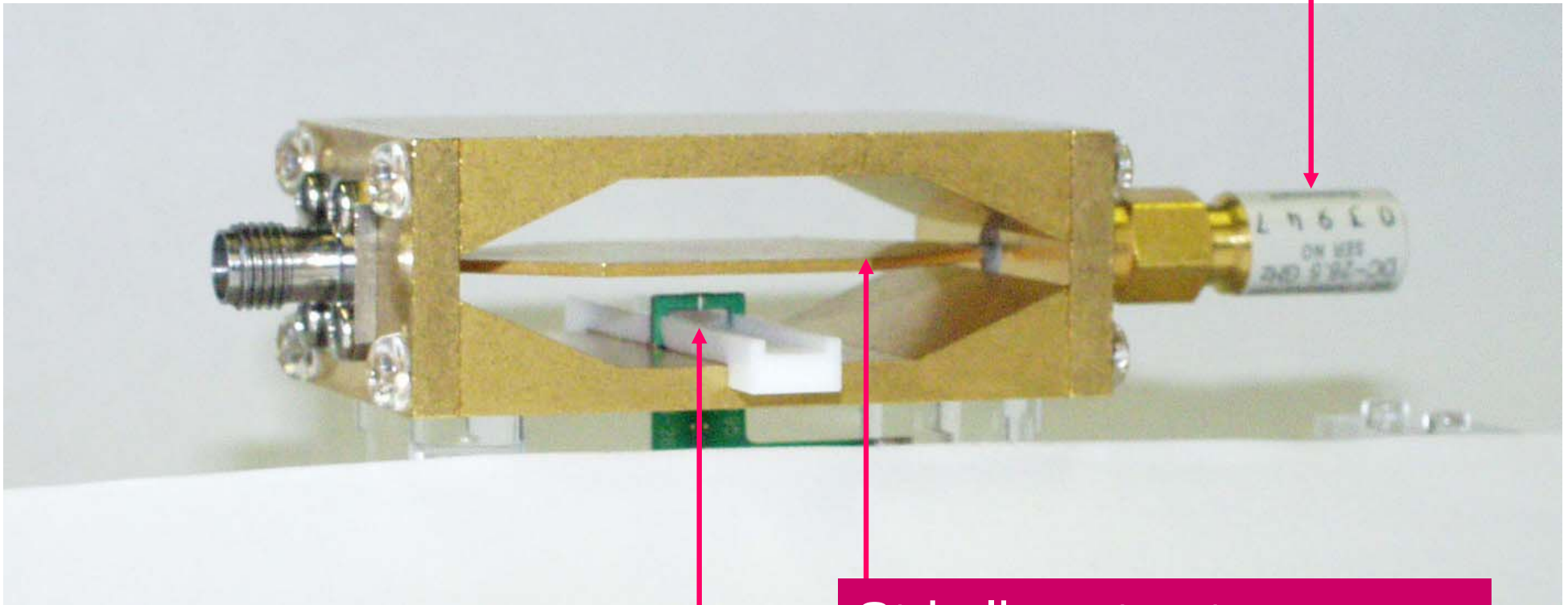
M. Yamaguchi et al.
T. Mag. Soc. Jpn.,
3 (2003) 137-140

Also
Ryowa Electronics Co.
Model PMM-9G1

9GHz measurement jig

Loaded end:

Yielding **TRAVELING** EM field



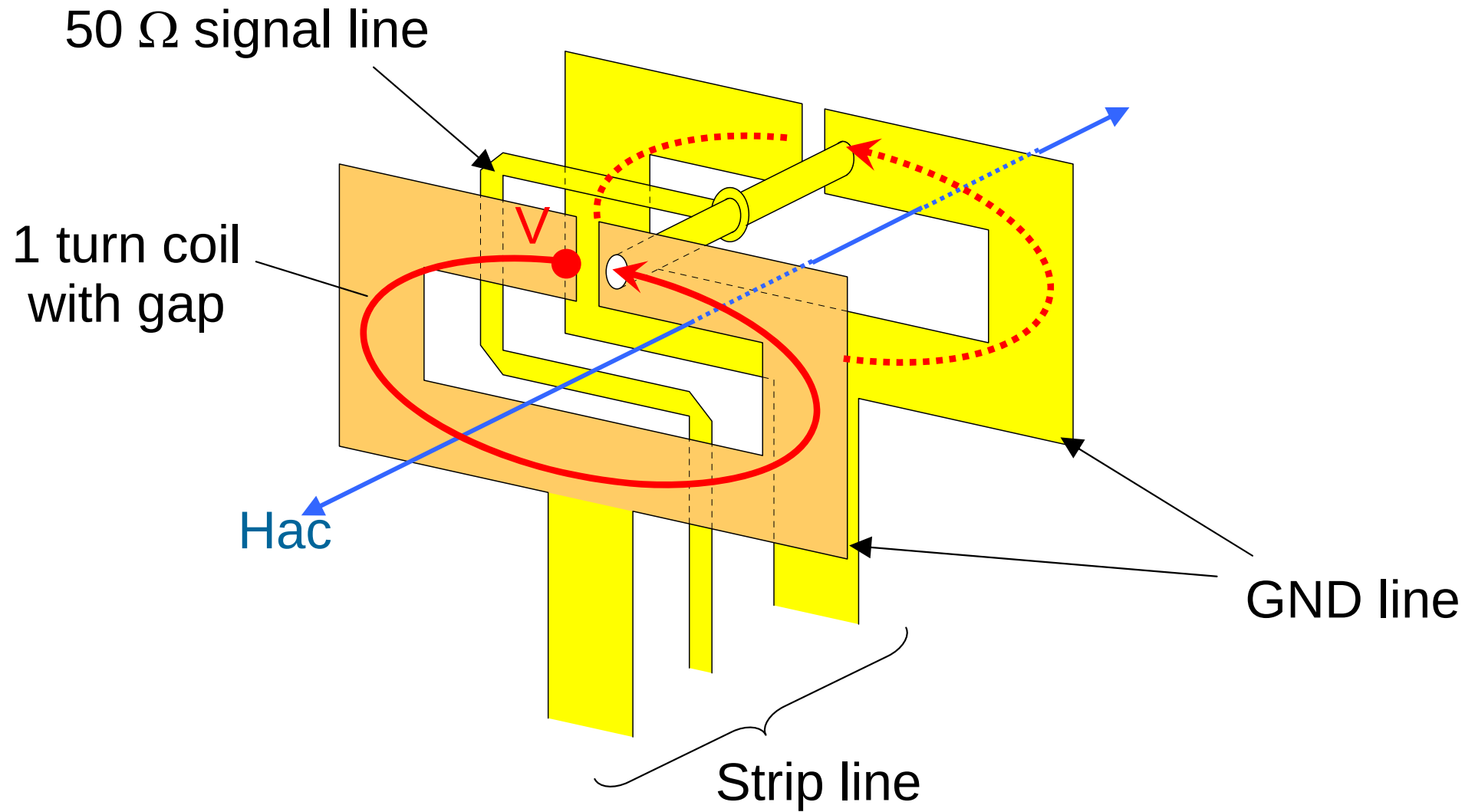
Centered pick-up coil arrangement

Improved EM uniformity at
the coil window

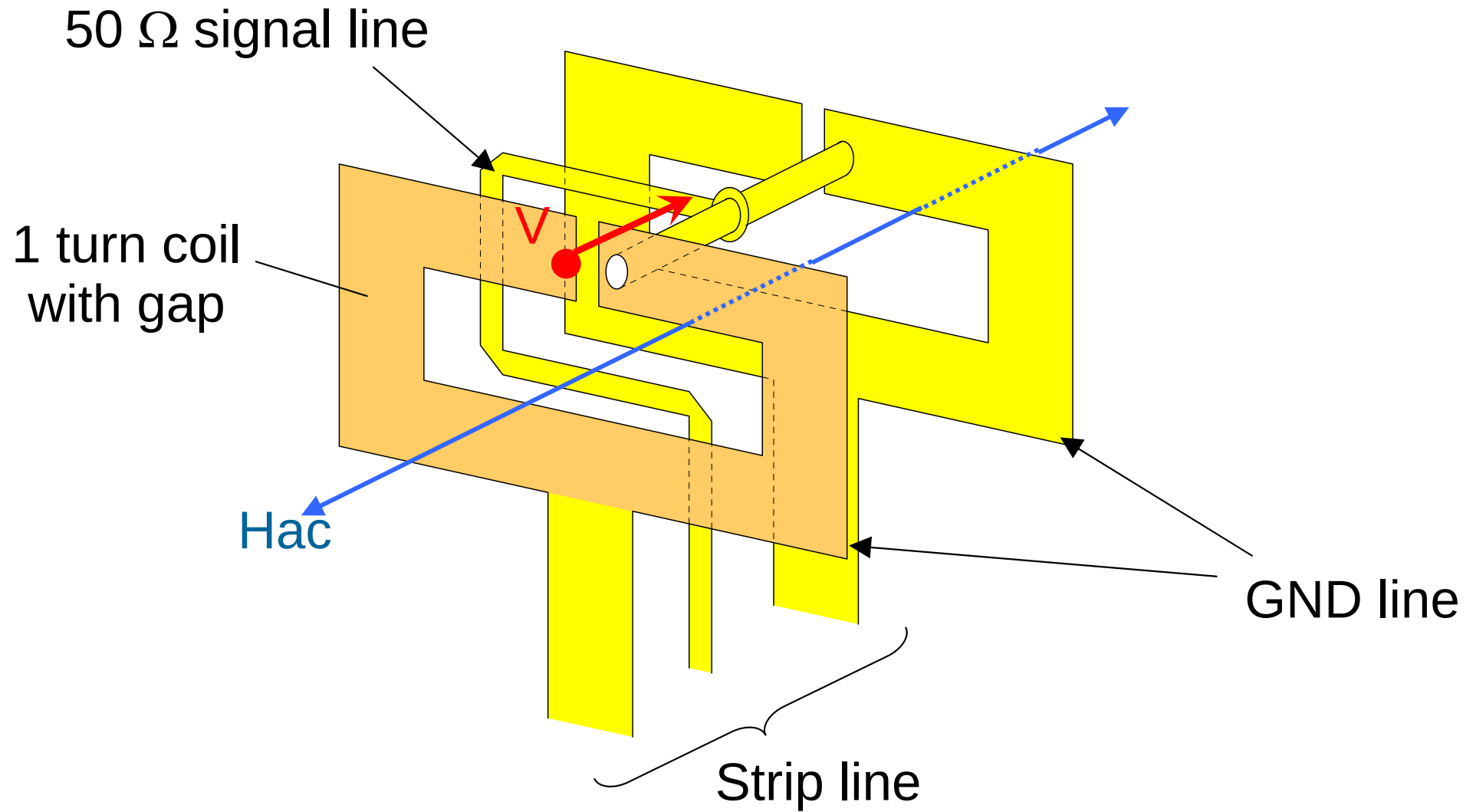
Strip line structure
(Side-open TEM cell)

Improved EM uniformity
throughout the jig

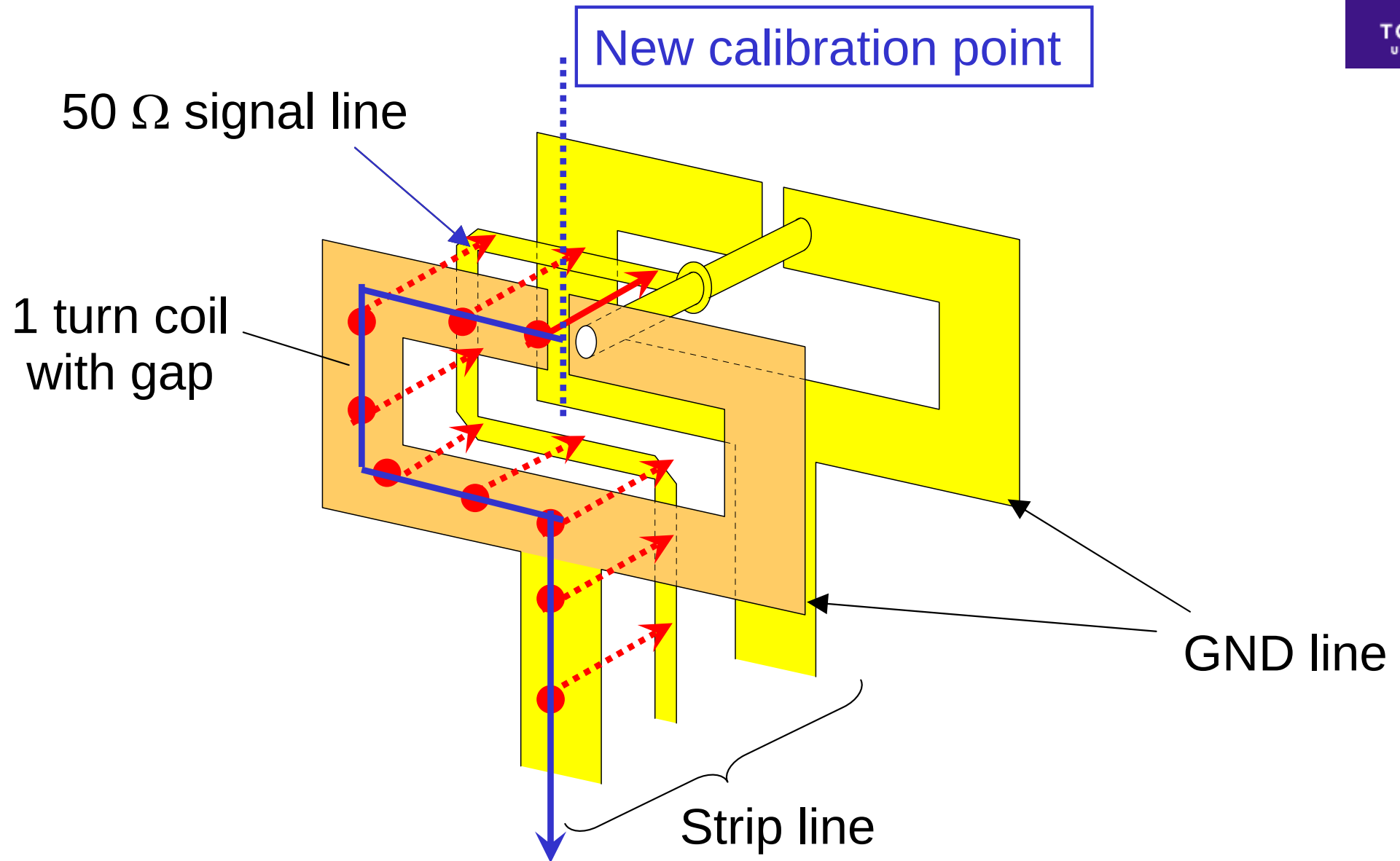
Planar Shielded-loop coil



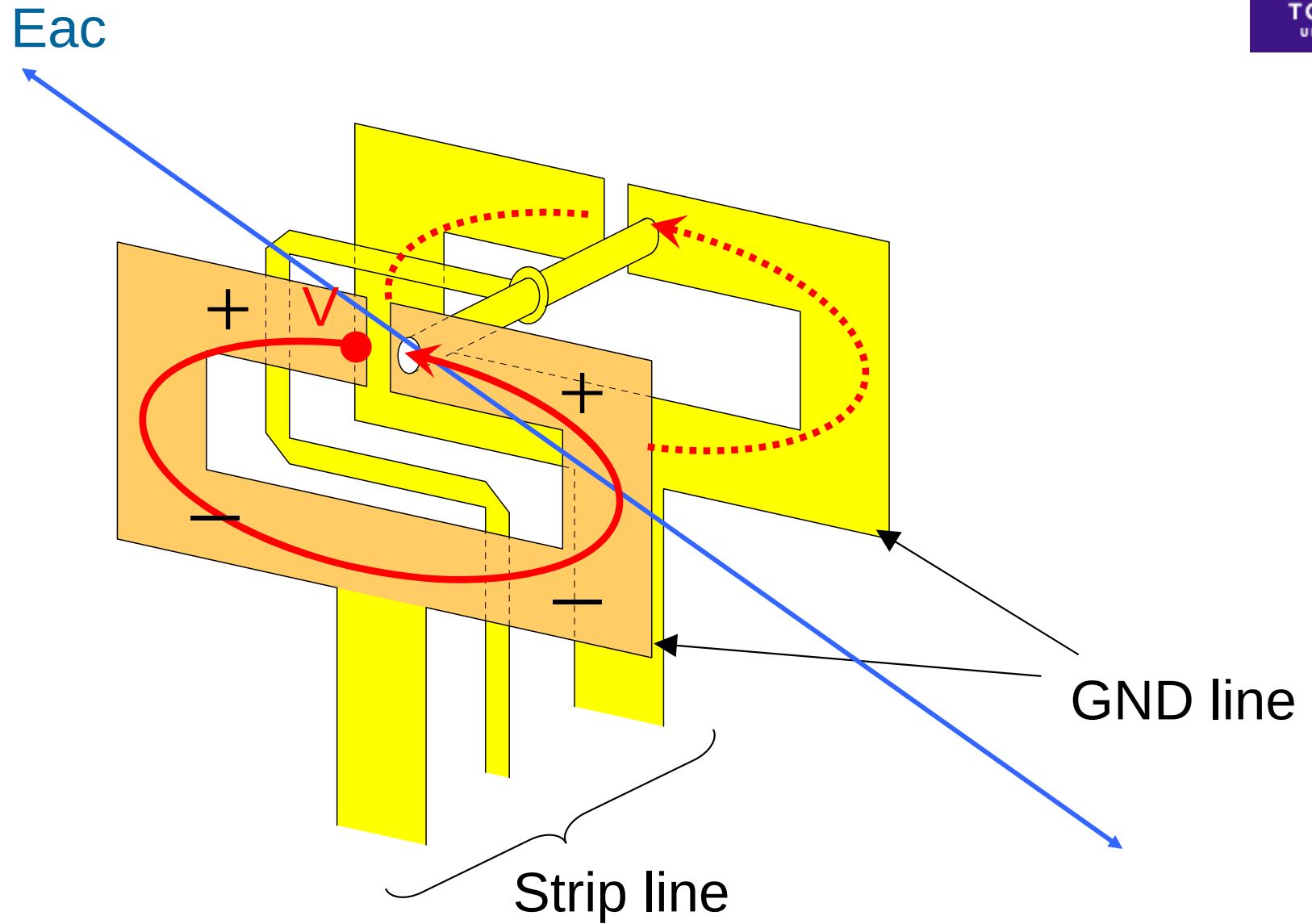
Voltage transfer along the strip line, I



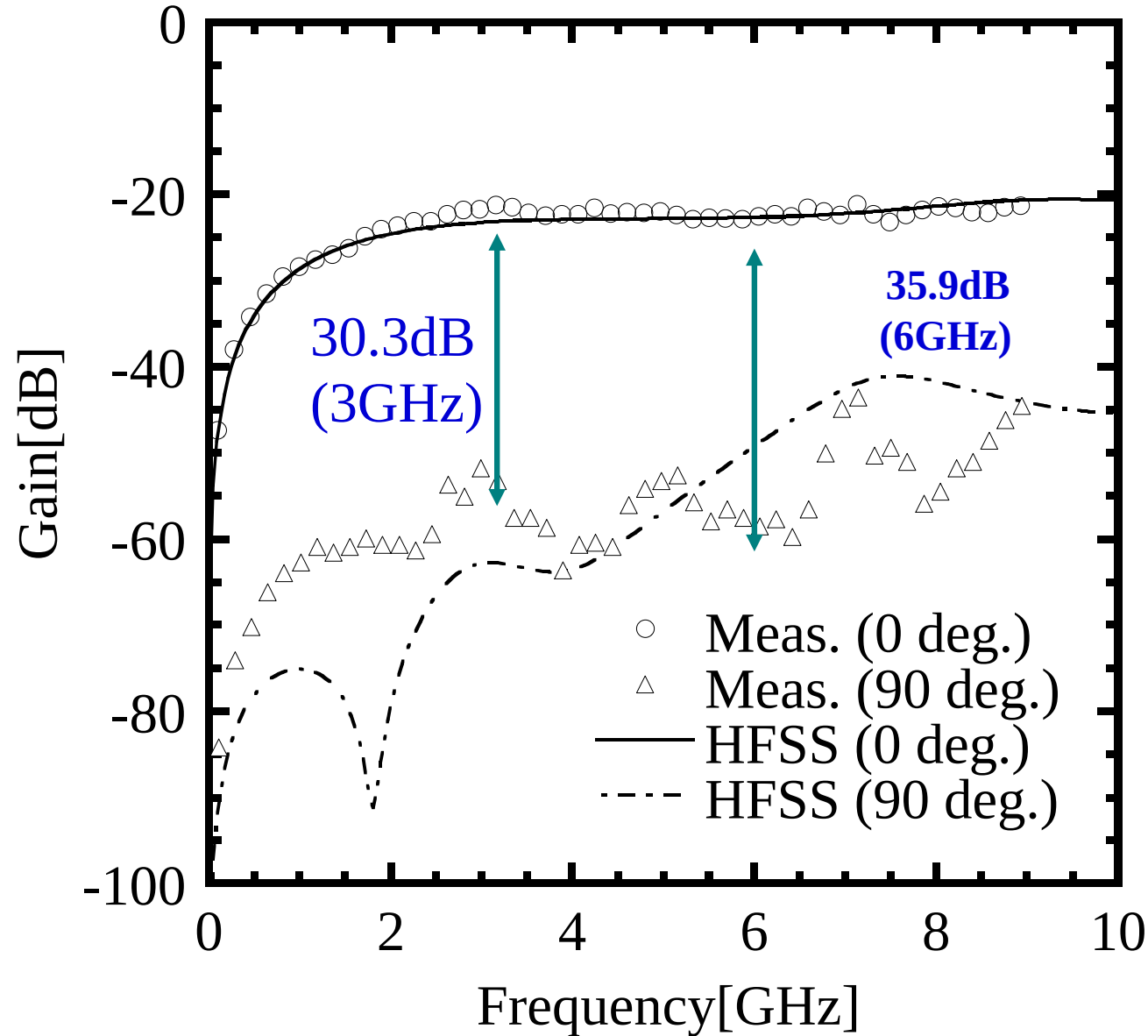
Voltage transfer along the strip line, II



E-field Voltage Suppression



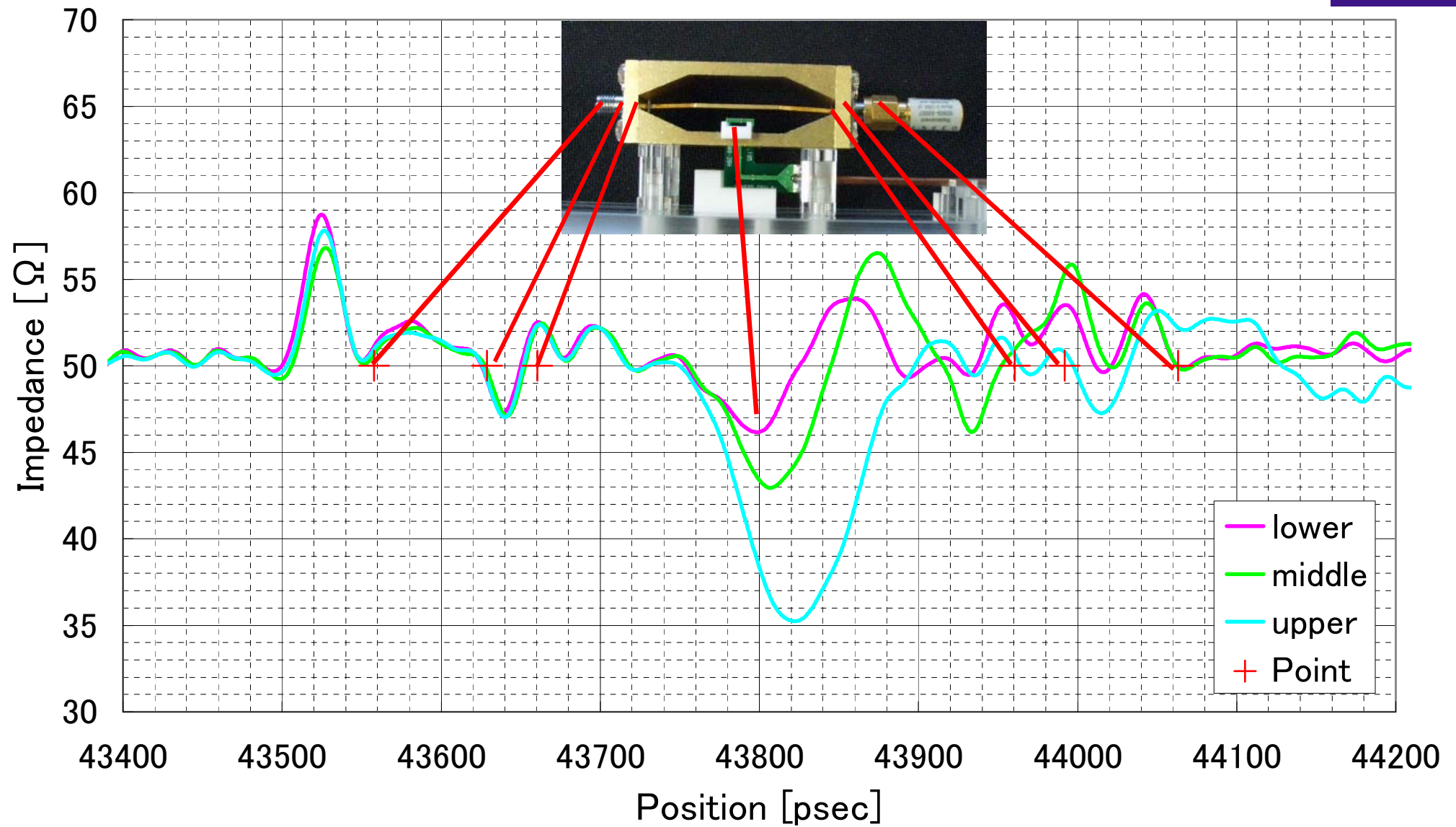
E-voltage suppression



Comparison of E- and M- voltages extracted by simulation & experiments.

Simulated by ANSOFT HFSS Ver. 8.0.21

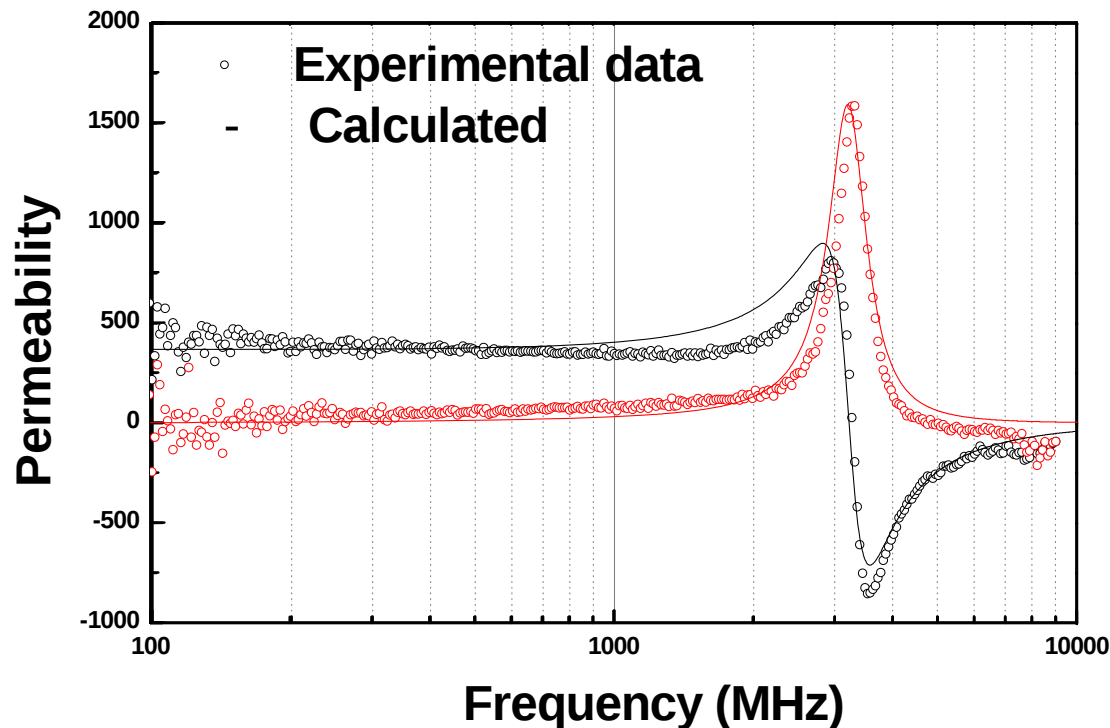
TDR Profiles



Validity check



1. Comparison with L.L.G. equation



FeCoBN:
thickness 978 nm, $4\pi M_s \sim 22\text{kG}$, $H_c \sim 5\text{Oe}$,
 $H_k \sim 60\text{ Oe}$, resistivity $\sim 73.8\ \mu\Omega\cdot\text{cm}$

By Prof. J-R Kim, Hanyang Univ., Korea

2. Int'l cross measurements

**Tohoku U, Japan
(Yamaguchi)**

Frequency domain
TEM cell/Pick-up coil

NIST, USA (Silva)

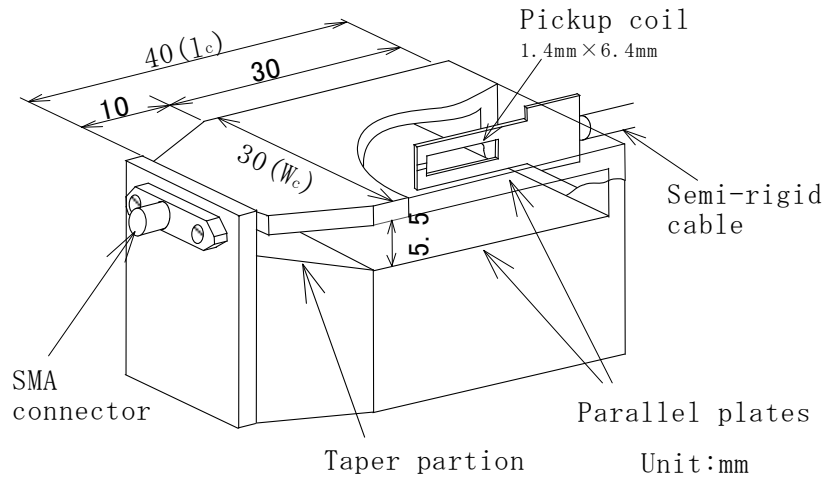
Time domain
Coplanar line

CEA, France (Acher)

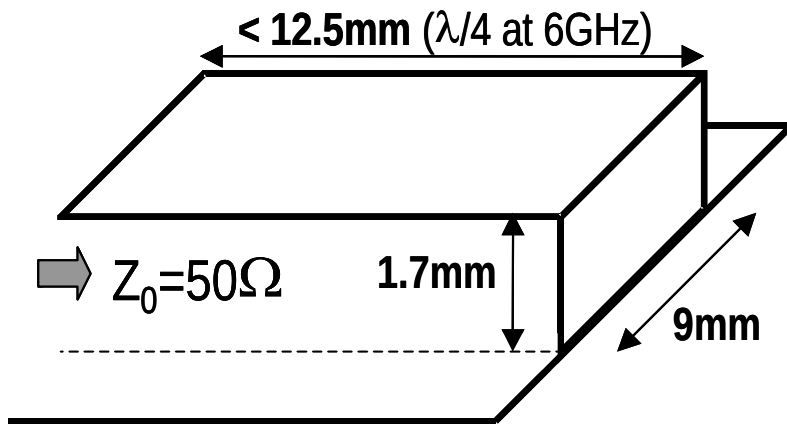
Frequency domain
Microstrip line

FMR frequencies agreed
within the error of 15%

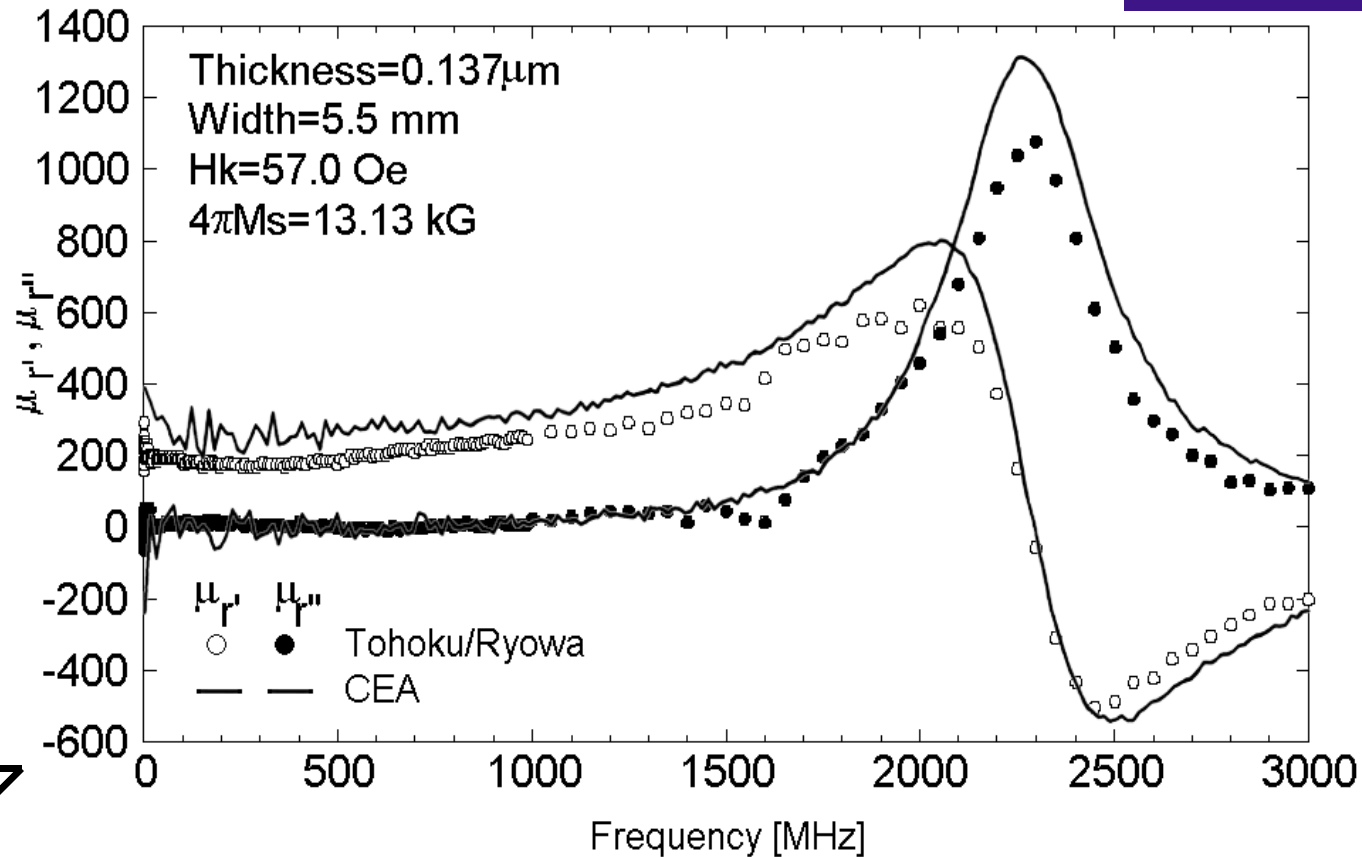
Int'l Cross Measurements, I



A jig for the pickup coil method.

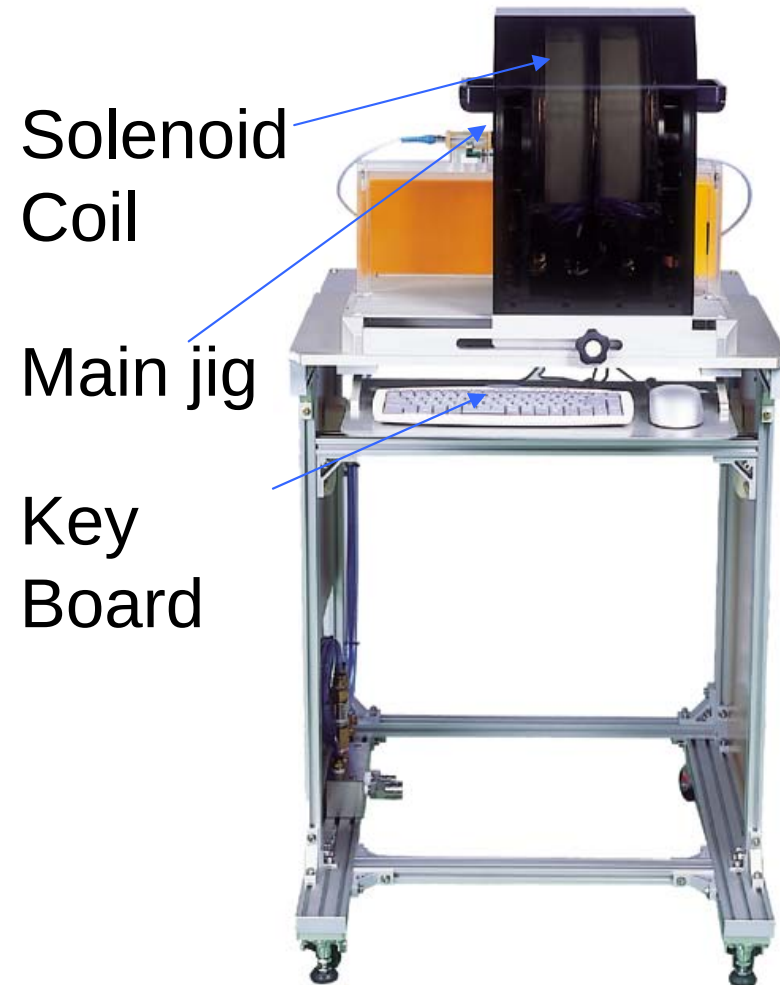
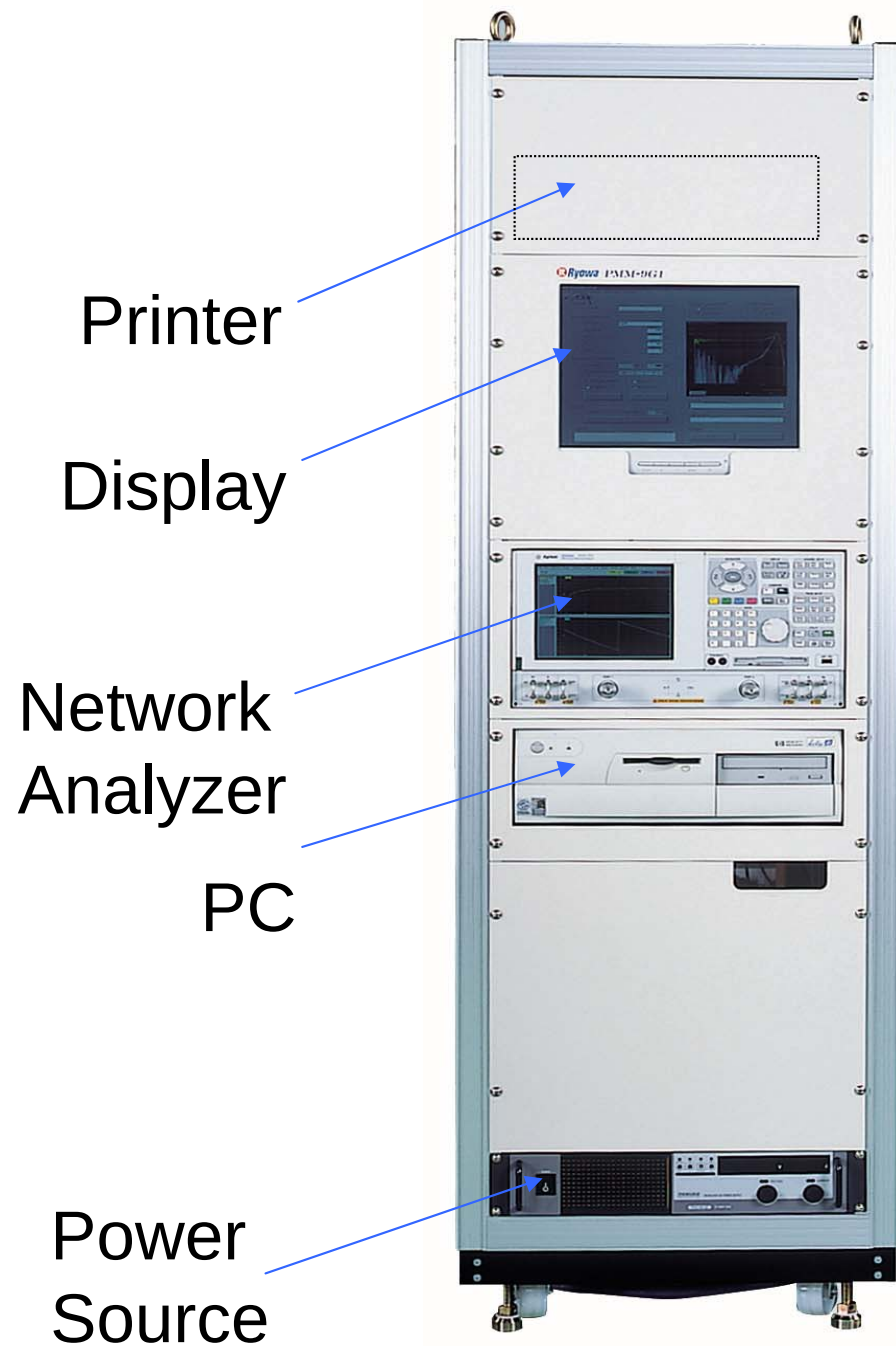


A jig for the transmission line method.



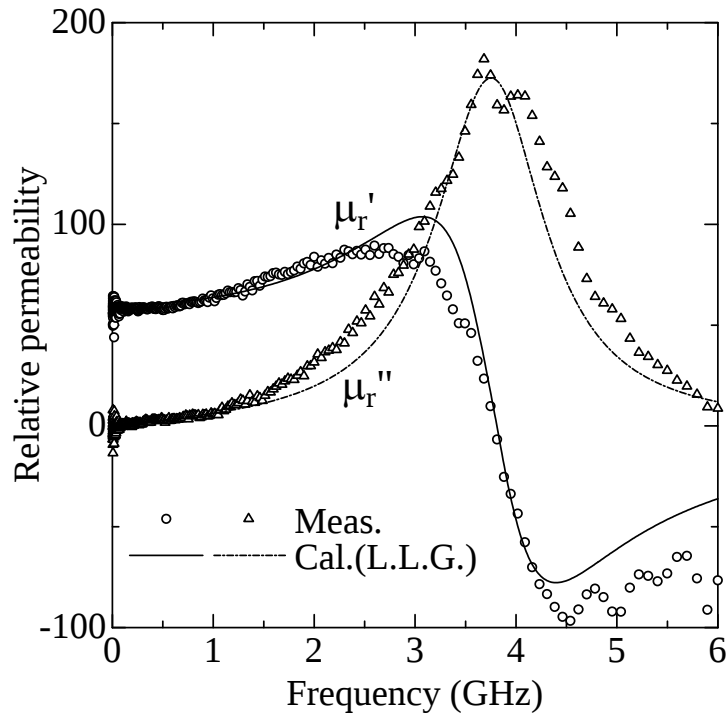
on a CEA-made 0.14 μm thick CoNbZr film.

Completed System (PMM-9G1, by Ryowa)



*M. Yamaguchi et al, IEEE Intermag2003, EA-03,
Boston USA April 2003.*

Granular films



CoZrO

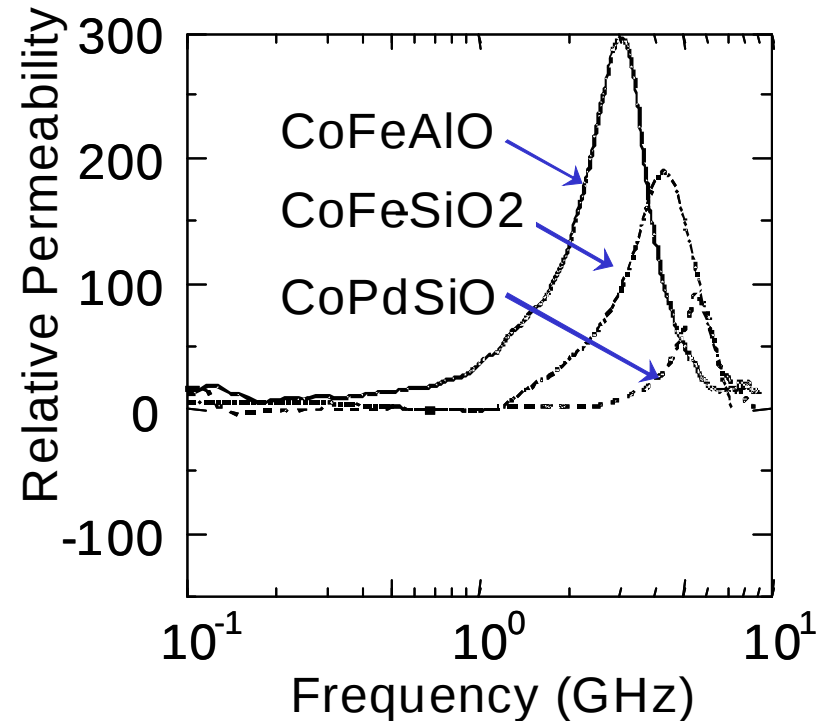
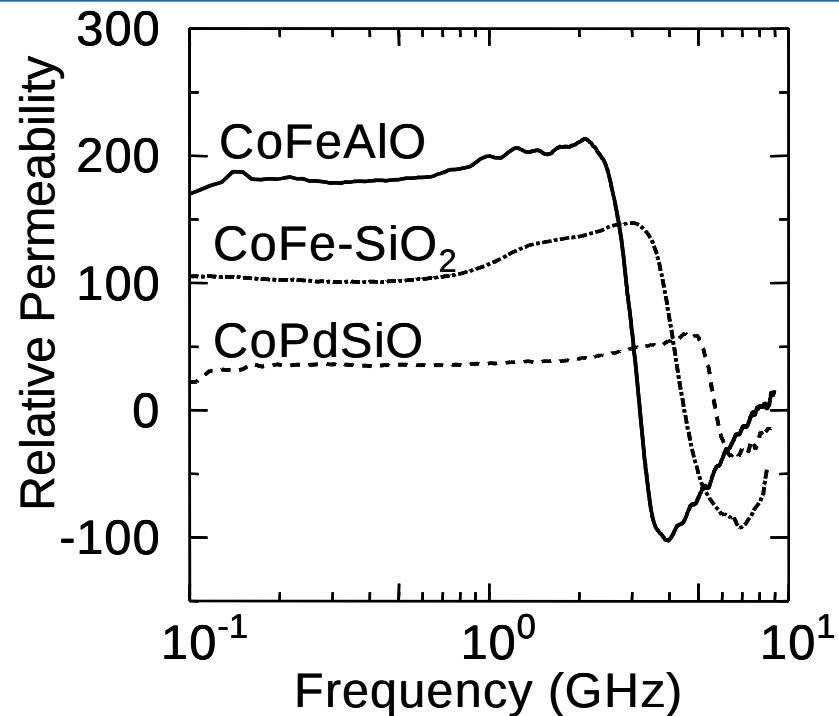
Thickness $1.82\mu\text{m}$, Resistivity $1800\mu\Omega\text{cm}$

S. Ohnuma et al, 25th Annual Conference on Magnetism in Japan, 25pC-1, (2001.9).

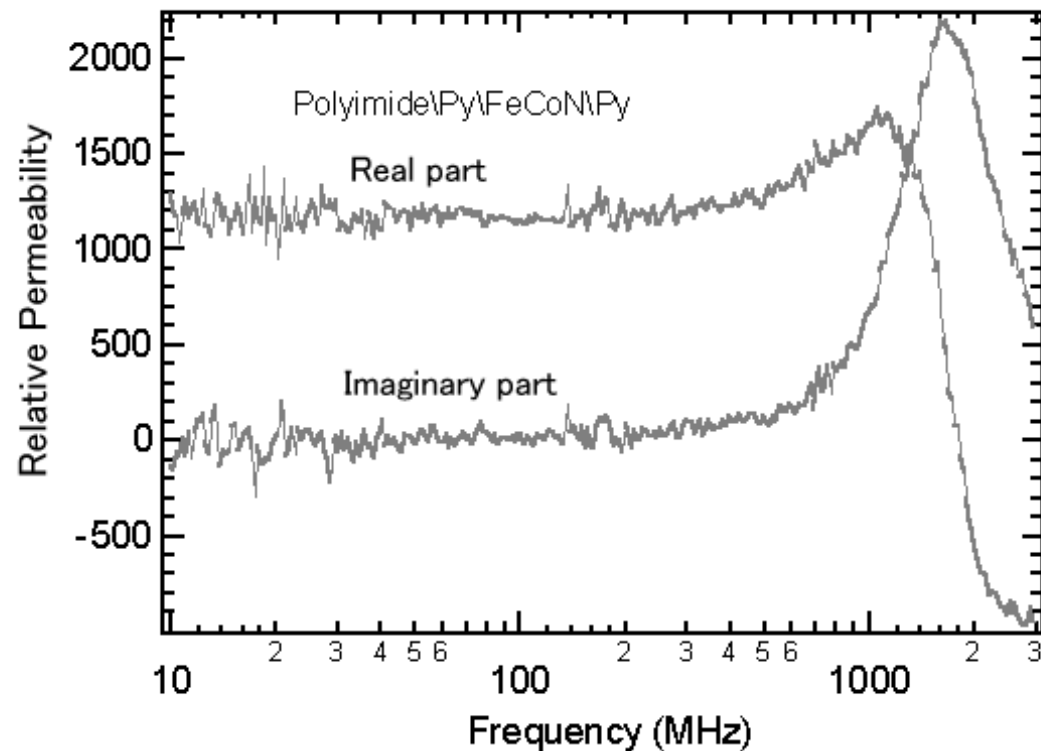
CoFeAlO: S. Ohnuma et al, *J. Appl. Phys.*, **85**, (1999) 4574.

CoFe-SiO₂: M. Munakata, et al, *J. Magn. Soc. Japan*, **28**, (2004) 240.

CoPdSiO: S. Ohnuma et al, *J. Magn. Soc. Japan*, **23**, (1999) 240.



Metallic films (FeCo-base system)

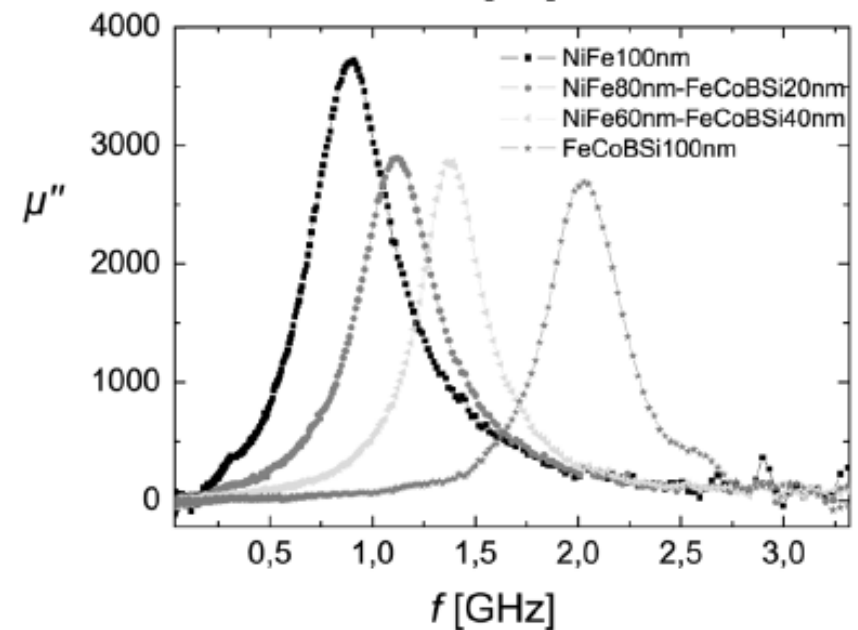
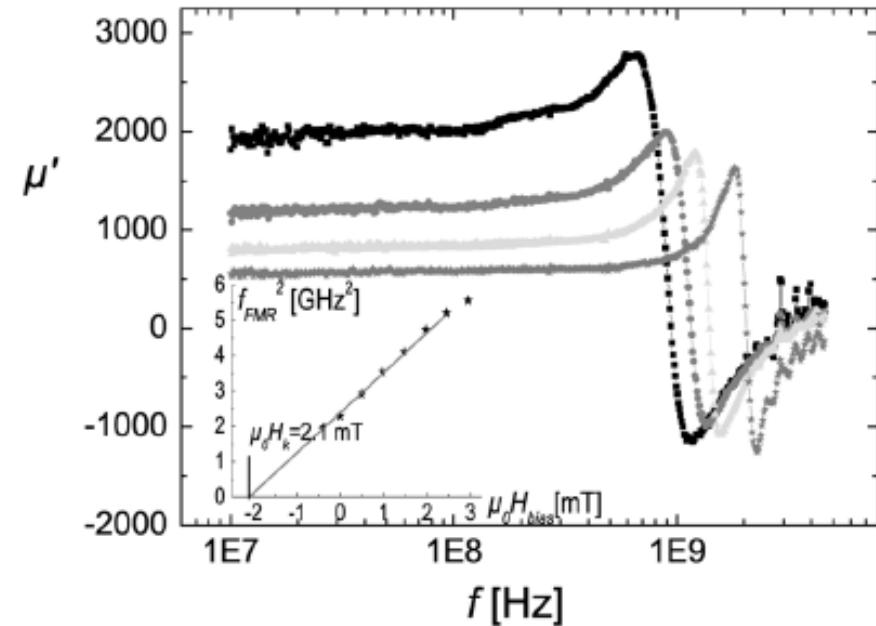


NiFe/CoFeN/NiFe

(by Prof. Wang, Stanford U)

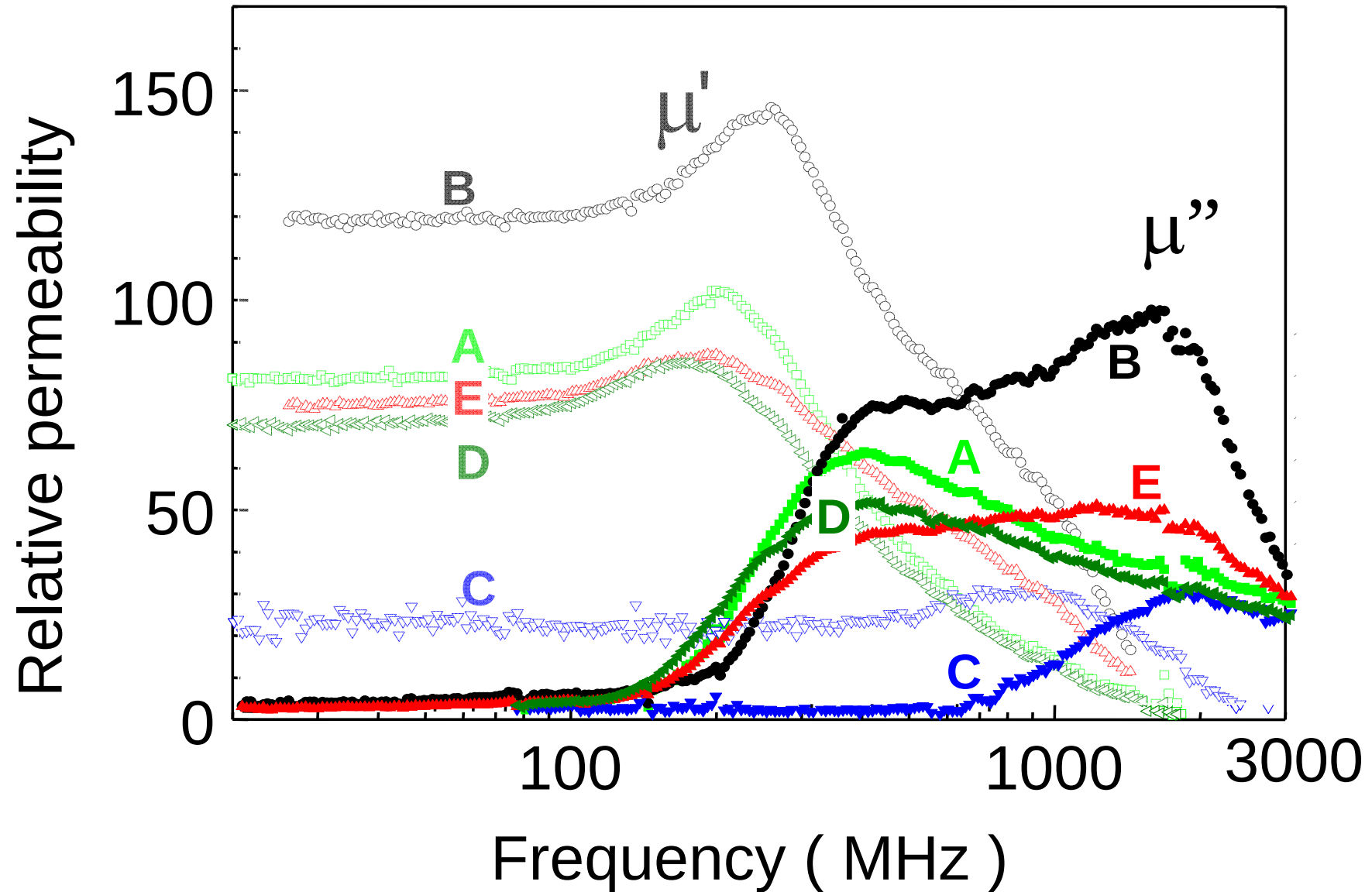
FeCoBSi(80 nm)/NiFe(20 nm) bilayer

A. Gerber, et al, IEEE Trans. Magn., **43**, 2624 (2007).

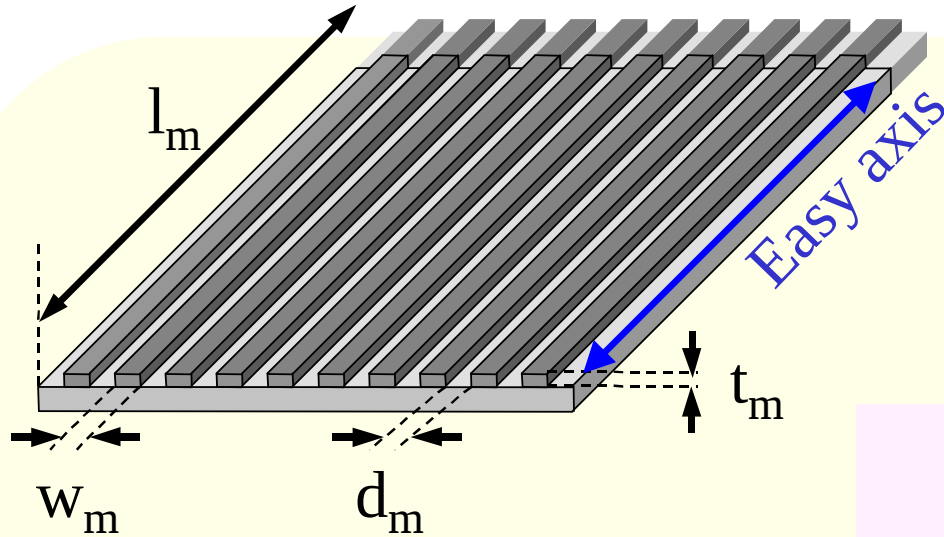


Spin-Spray ferrite films

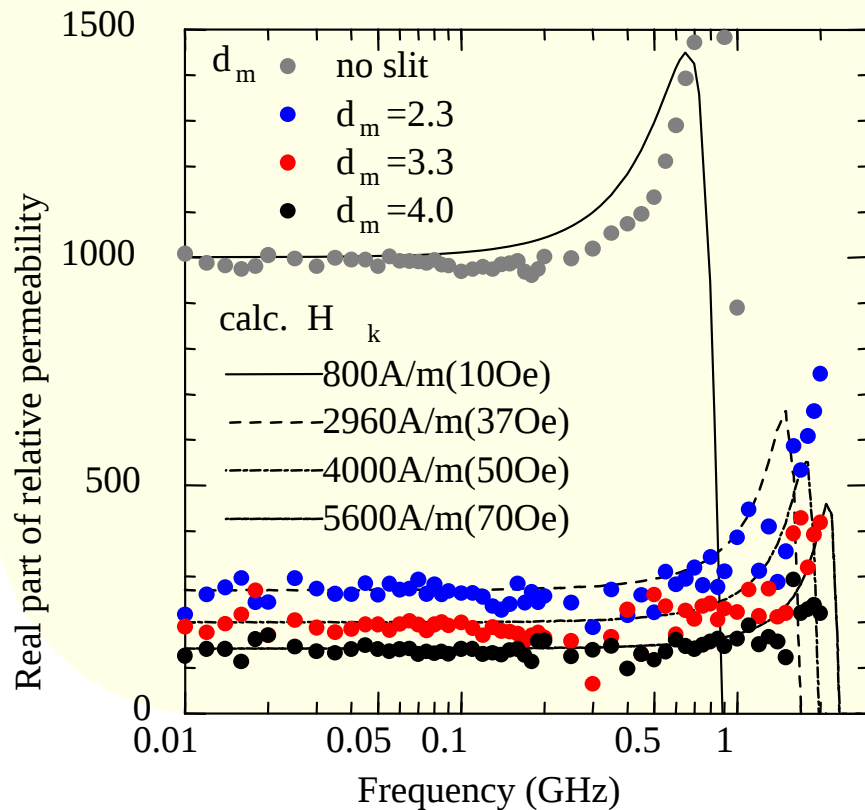
A, D : NiZn-Ferrite films, **B, C, E** : NiZnCo ferrite films



Slit works on magnetic film



$$\begin{aligned} l_m &= 4\text{mm} \\ w_m &= 20\mu\text{m} \\ t_m &= 0.2\mu\text{m} \\ d_m &= 2.3\mu\text{m}, 3.3\mu\text{m}, 4.0\mu\text{m} \end{aligned}$$



$$H_{keff} = H_k + N_d M_s$$

H_k : anisotropy field

N_d : demagnetizing factor

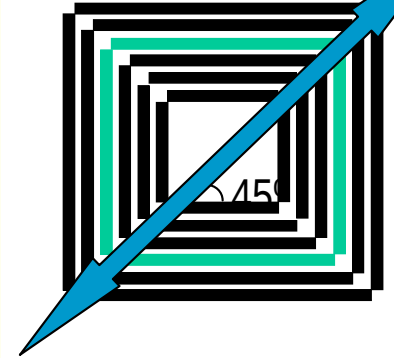
M_s : saturated magnetization

$$\mu_{eff} = \frac{M_s}{H_k + N_d M_s}$$

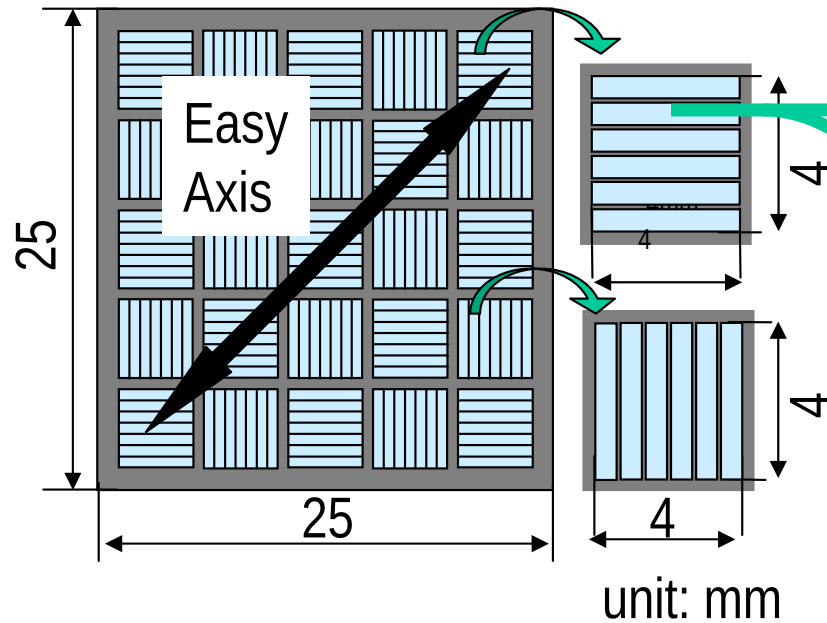
$$f_r = \frac{\gamma}{2\pi} \sqrt{\frac{M_s H_k + N_d M_s^2}{\mu_0}}$$

γ : gyromagnetic constant

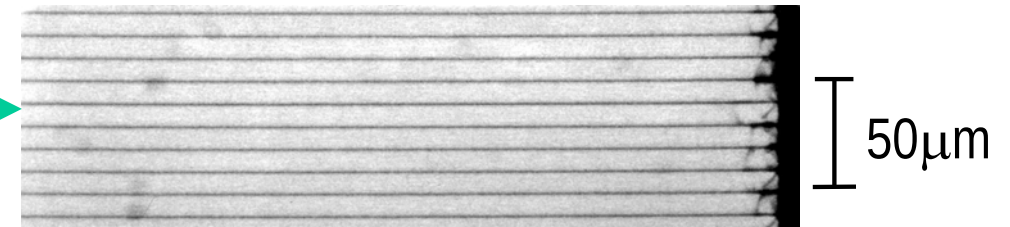
Intrinsic
easy axis



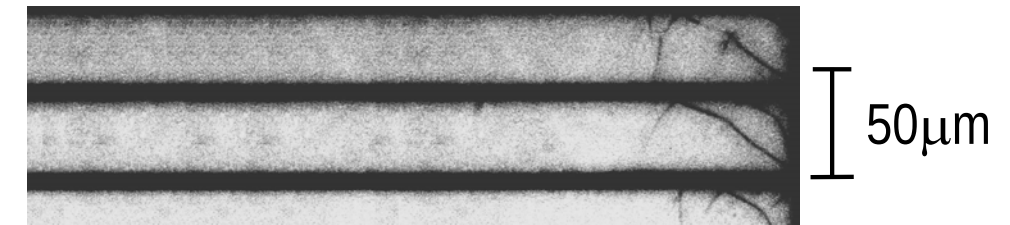
Observed domain structures (1)



Test pattern of bi-directional micro wire array



(a) 10 μm wide micro wire array



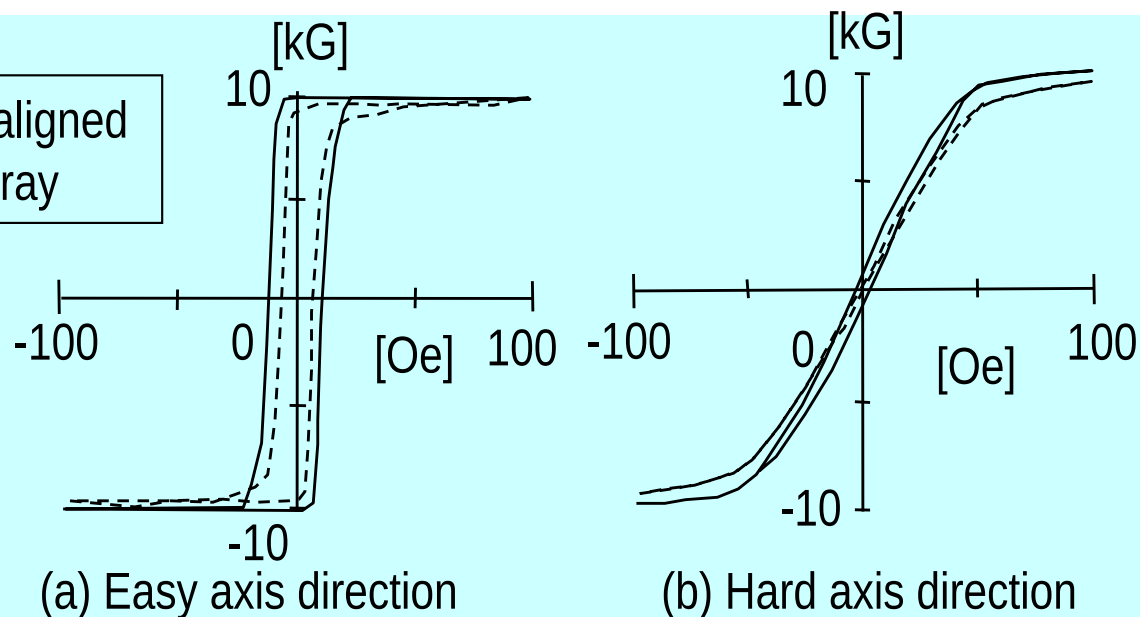
(b) 30 μm wide micro wire array

Observed domain structure.

0.1mm thick and 2mm long samples.

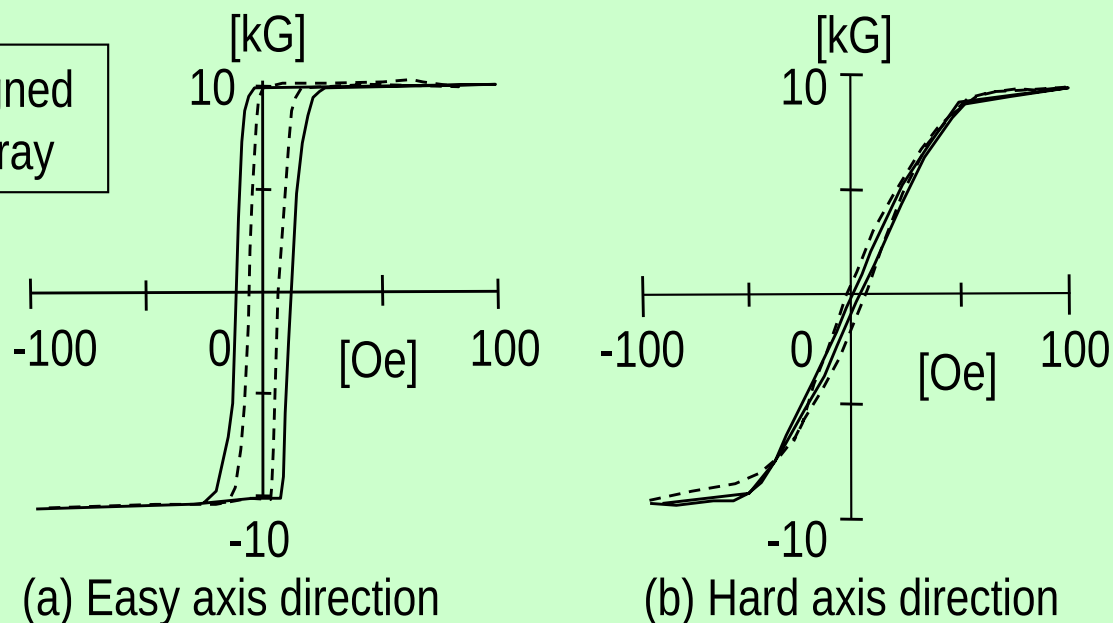
Hysteresis curves

Horizontally aligned
micro wire array



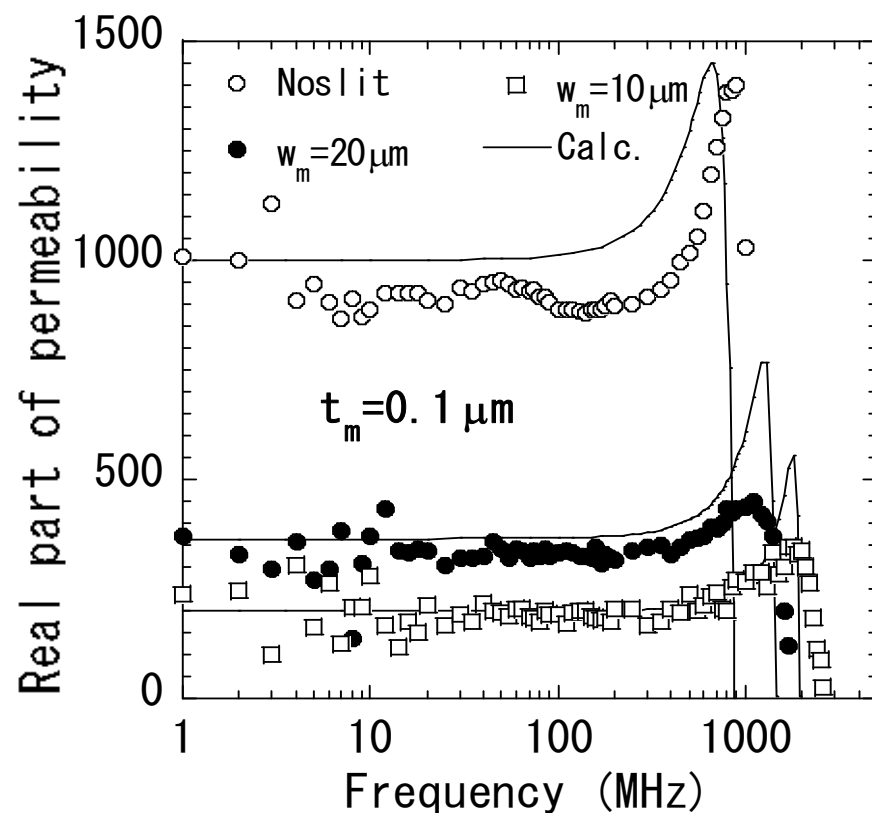
0.1mm thick
10 μ m wide
0.6 μ m spacing
2mm long

Vertically aligned
micro wire array

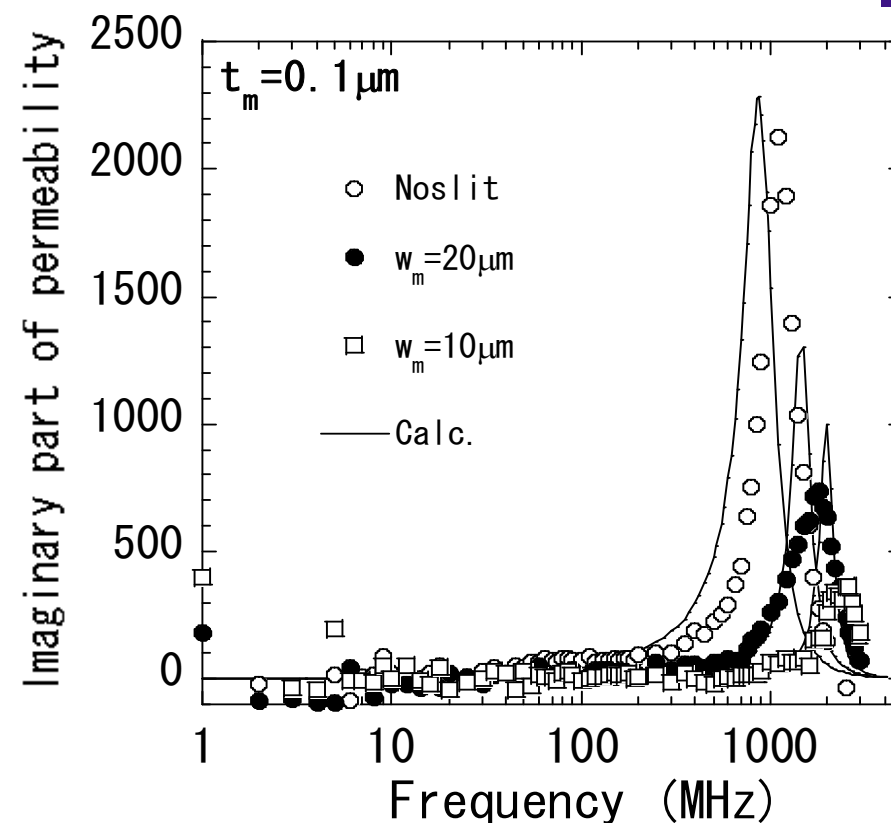


Broken lines:
before annealing
Solid lines:
after annealing

Frequency profile of complex permeability



(a) Real part



(b) Imaginary part

Width: varied, $0.1 \mu\text{m}$ thick, $0.6 \mu\text{m}$ spacing, 4mm long
no heat treatment

Possible advantages of magnetic thin-film inductors

■ Miniaturization

Magnetic film enhances magnetic flux.

■ Low coil loss

Coil length reduces with miniaturization.

■ Low eddy current loss in Si and SiGe

Magnetic flux is mostly associated with magnetic film.

■ Thin insulator between coil and Si

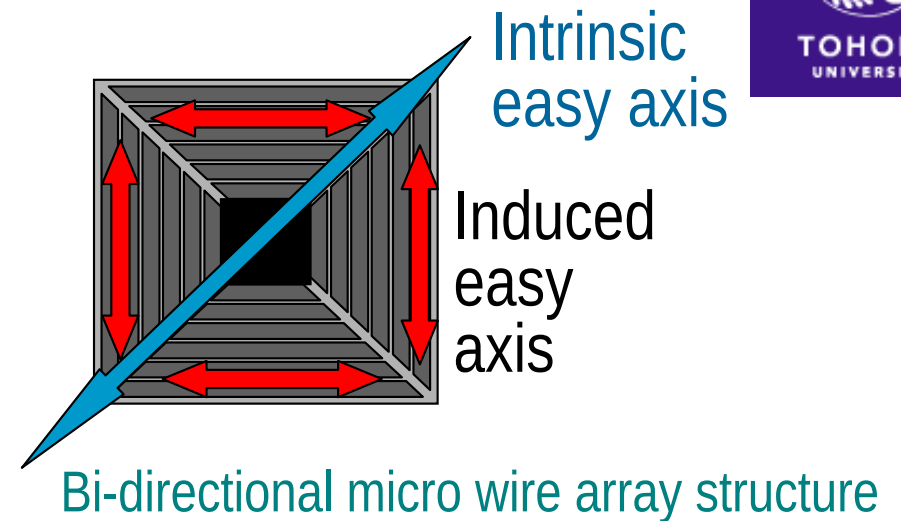
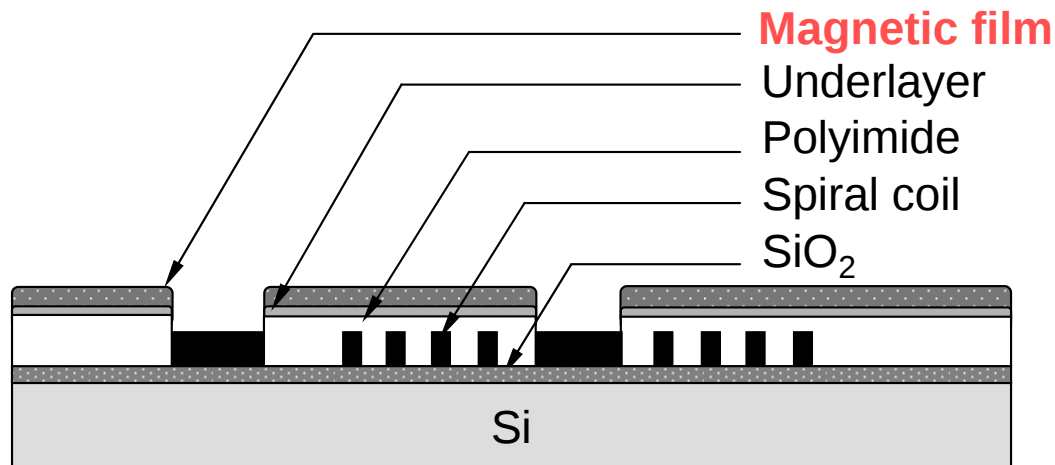
because low eddy current loss in Si.

■ High self-resonance frequency???

Size is small but magnetic film can be a electrode of a capacitor...

Toward
High efficiency

Spiral inductor

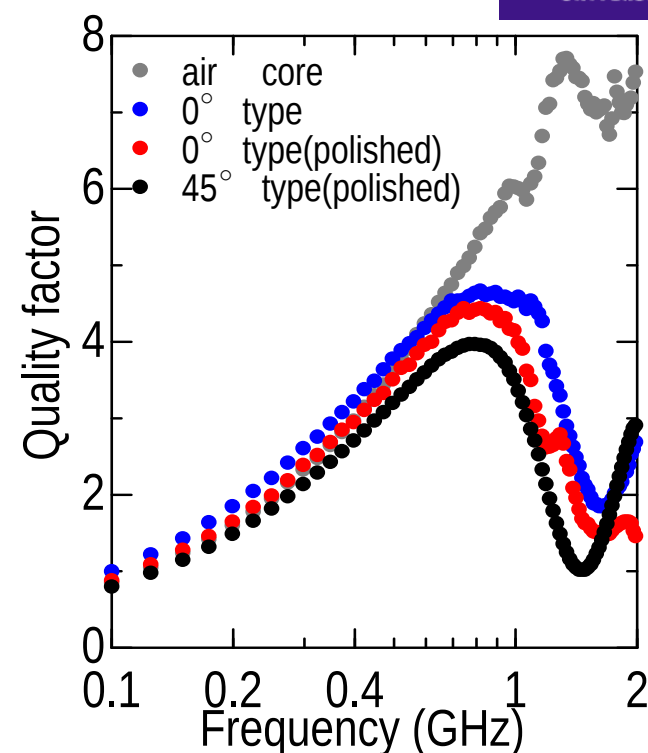
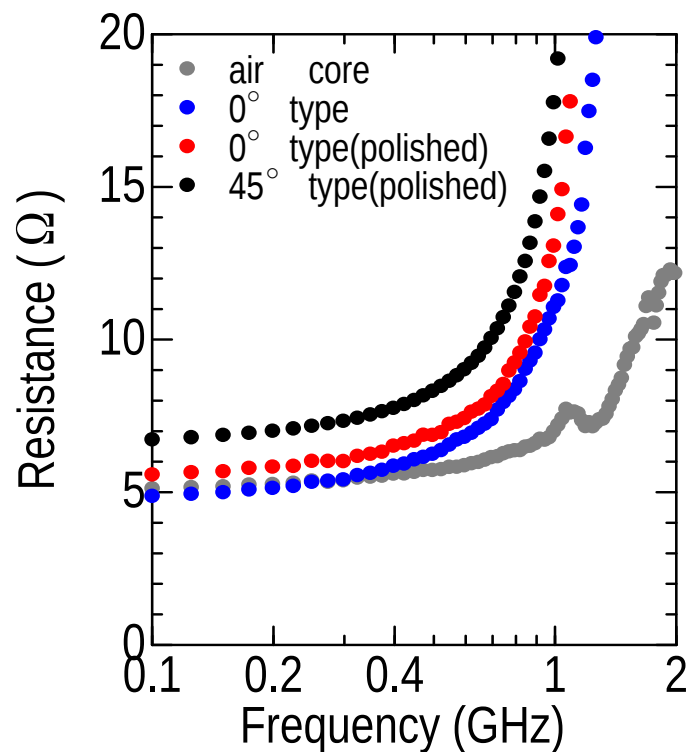
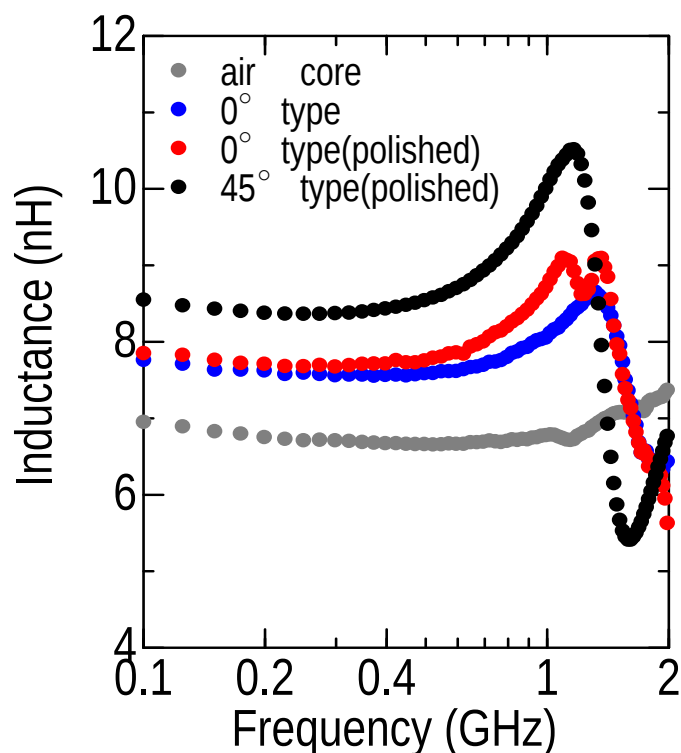


Coil	Spiral:	4 turns
	Width:	11.0 μm
	Spacing:	11.0 μm
	Thickness:	2.6–3.0 μm
	Area:	337 x 337 μm^2
Magnetic thin film	Thickness:	0.1, 0.3 μm
	Wire array patterns:	None, Parallel or Micro wire array
Substrate	Thickness:	600 μm

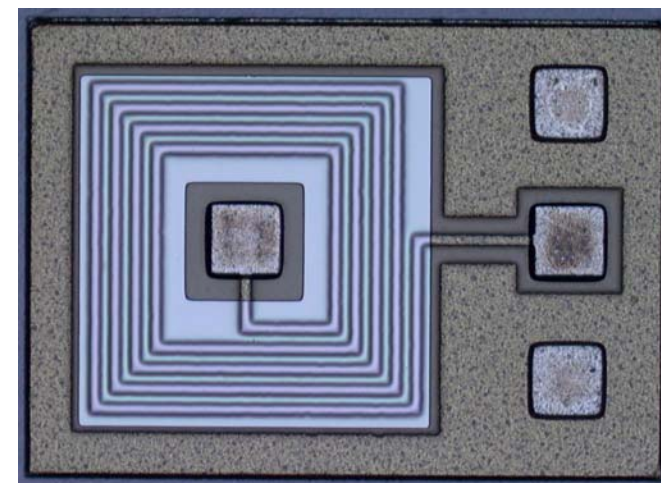
Advantages:

- Enhance the air-core inductance up to 100%
- Post Si process compatible
- by micro wire array structure:
 - Enhance FMR frequency
- by bi-directional wire structure
 - Utilize 100% area of magnetic film

Non-patterned CoNbZr film inductor

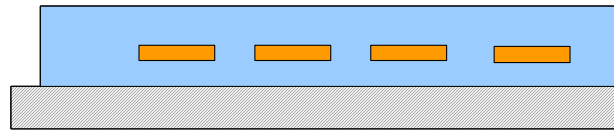


■ L=10.1nH (+ 50%) but R=19.2 Ω and Q=3.4

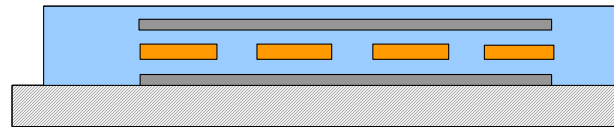


Sandwich structure thin film inductors

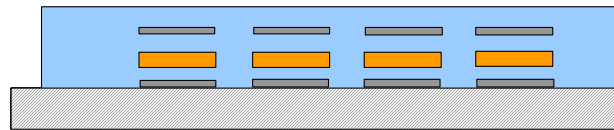
-  Coil
-  Magnetic film
-  Insulator
-  Substrate



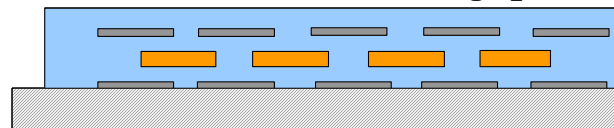
(i) **Air-core**



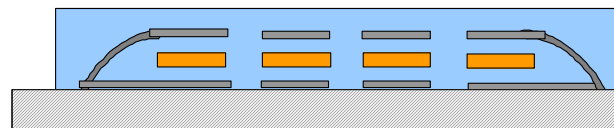
(ii) **Plain**



(iii) **Aligned** : The slits on magnetic film faces to the coil gap.

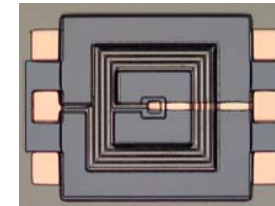
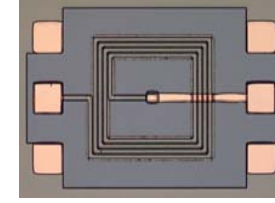
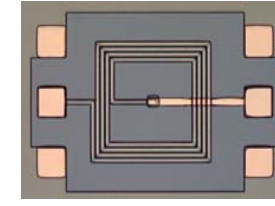
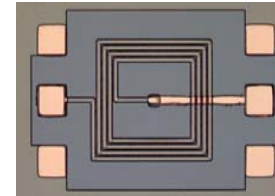
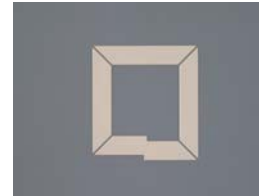
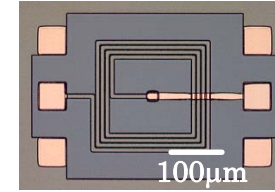


(iv) **Shifted** : The slits are shifted by a half coil pitch



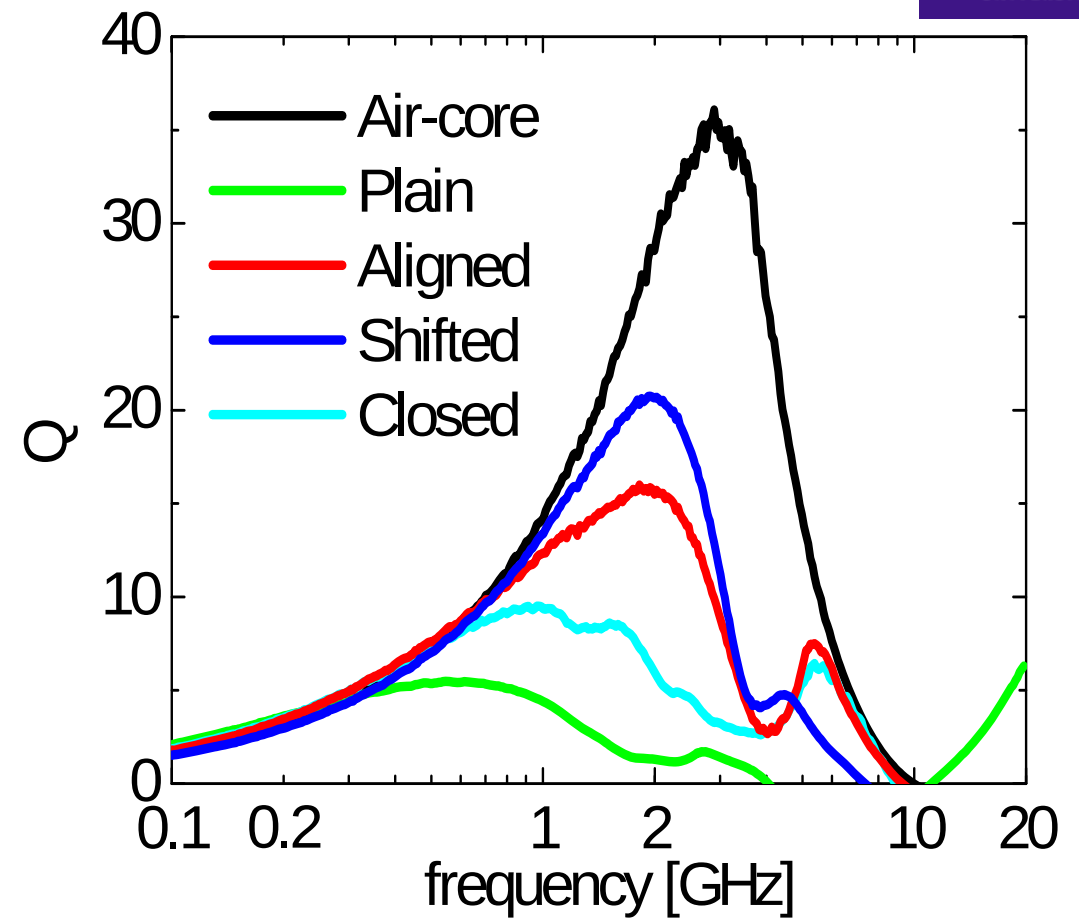
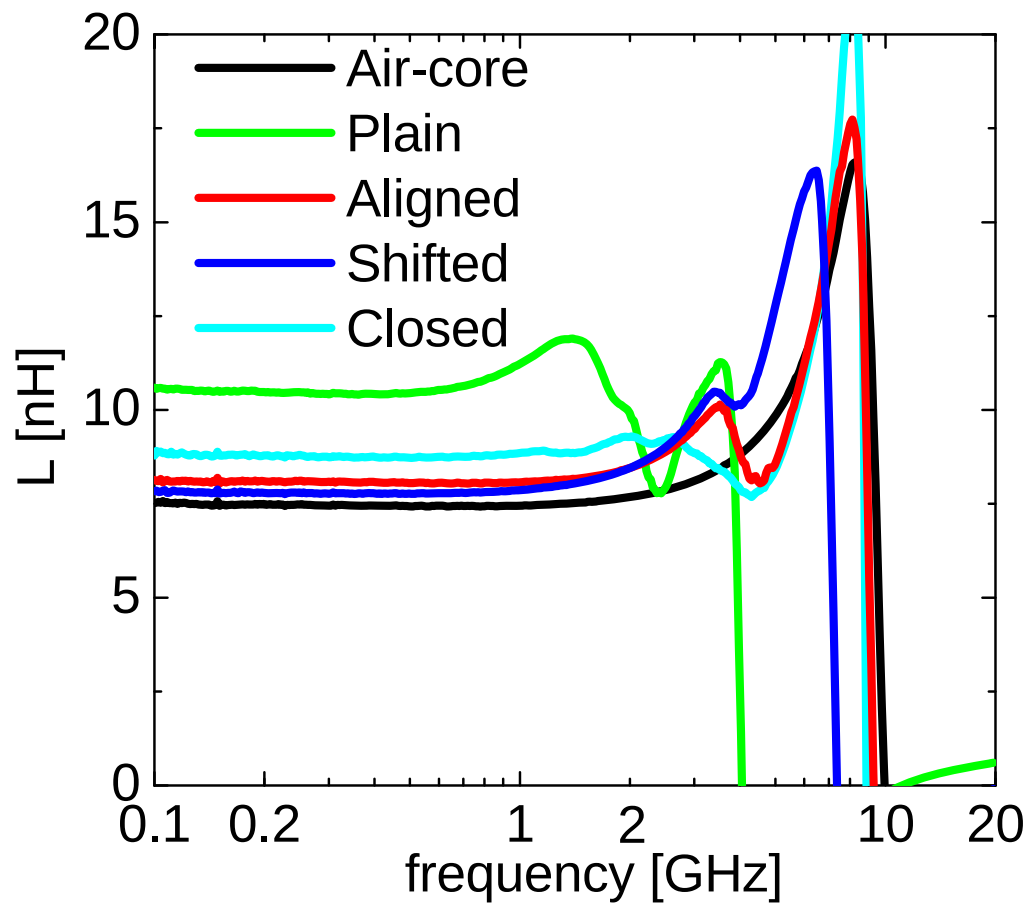
(v) **Closed** : The top and bottom magnetic layers are terminated at the edges

(a) Cross sectional structure

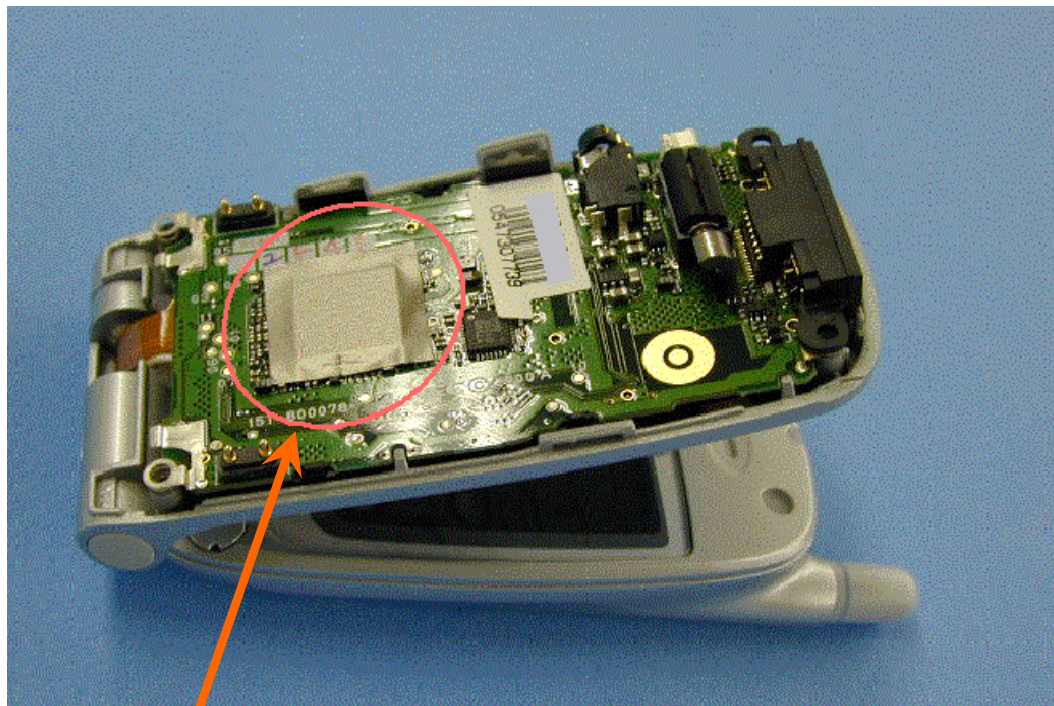


(b) Magnetic film patterning (c) Outlook of the completed inductor

L & Q



Intra-EMI problems of modern IT equipments



Complimentary: NEC-Tokin Co.

Noise Suppression Sheet (NSS)

- To reduce unexpected signal to noise couplings
- By means of FMR loss generation in magnetic materials

High Freq. operation

- Signal and communication frequencies conflict.
- Wave length becomes similar to device and Equipment size.

High Density Packaging

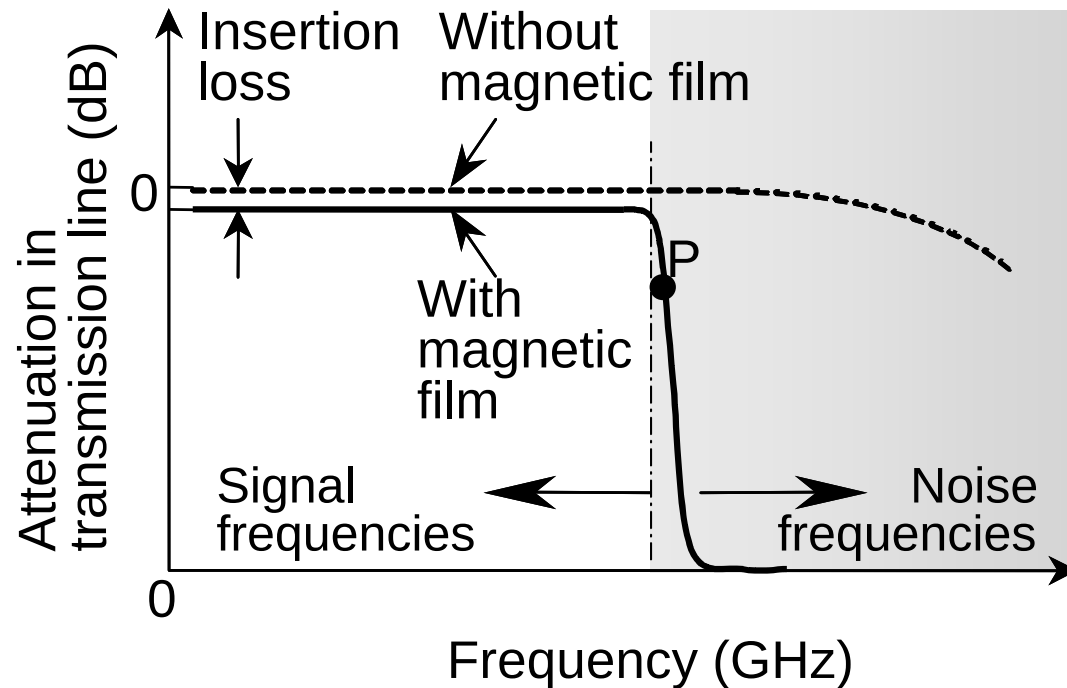
- For further miniaturization
- For new device installation (camera, et al)

Low Power drive

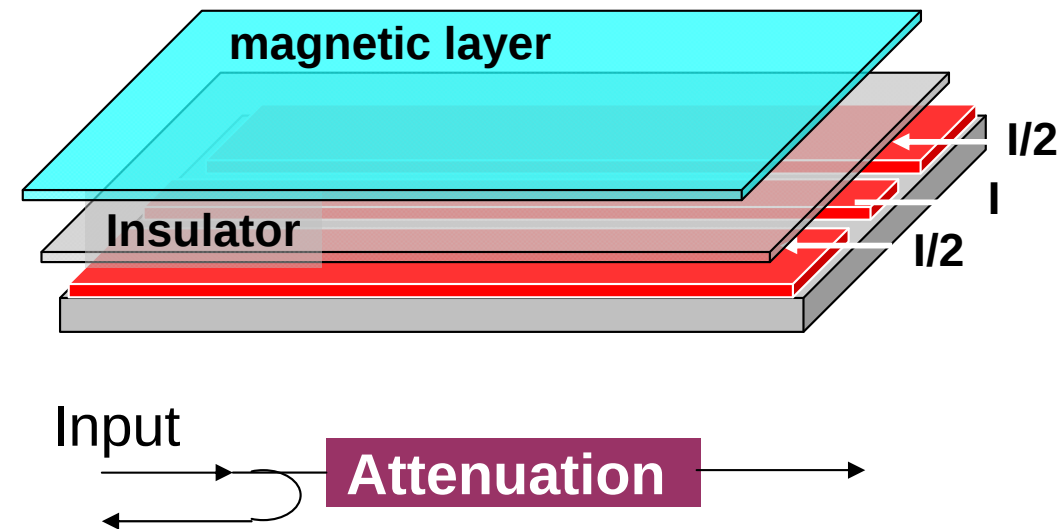
- Low S/N ratio
- radiating wave source (Common Mode Current)

Idea of thin film noise suppressor

Ideal frequency profile



Schematic diagram



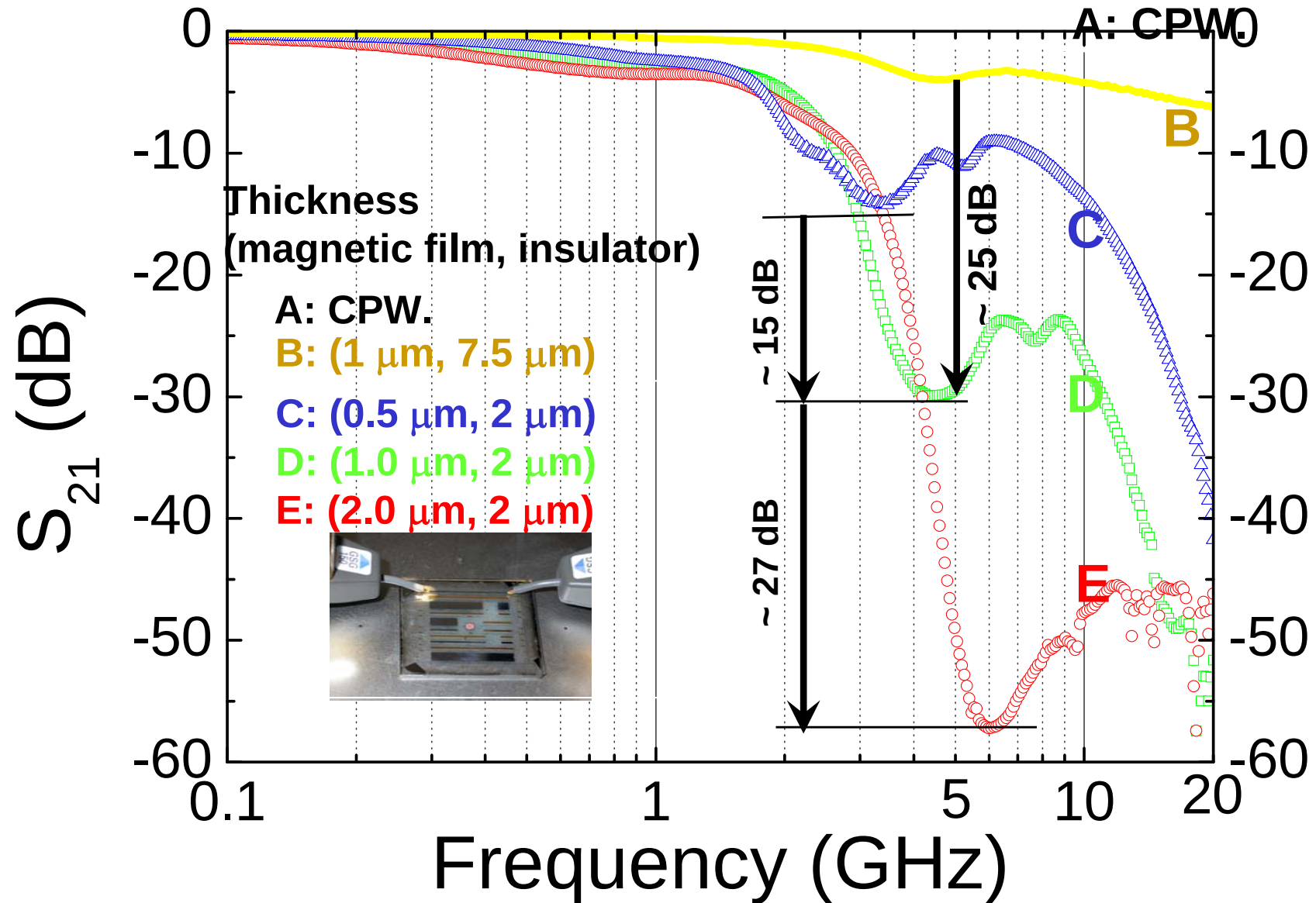
Reflection, S_{11} Transmission, S_{21}

$$P_{\text{loss}}/P_{\text{in}} = 1 - (|S_{21}|^2 + |S_{11}|^2)$$

Gap length vs. transmission properties

CoNbZr magnetic film

15 mm(L) x 2 mm(W) x 0.5, 1, 2 μ m(T)



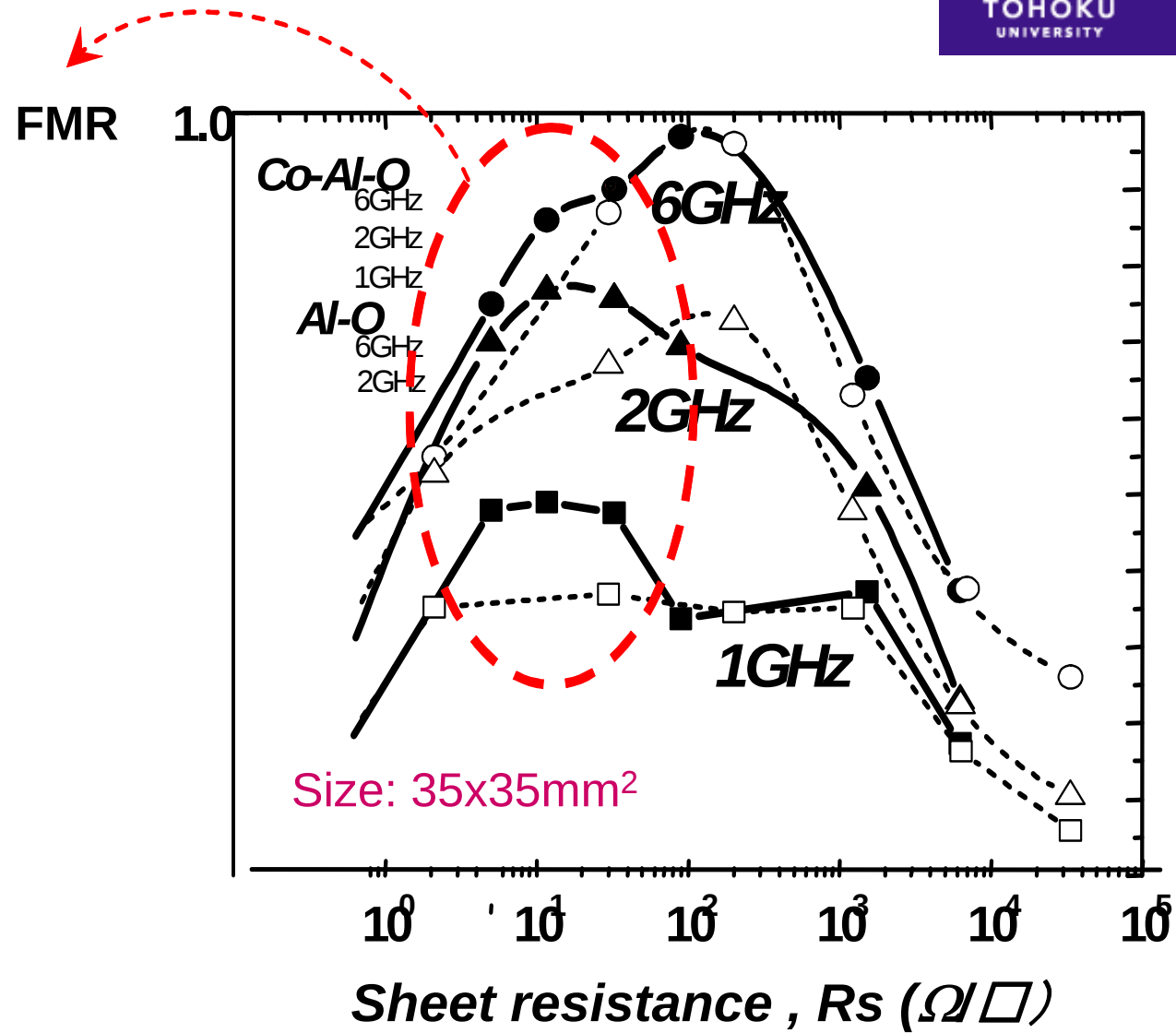
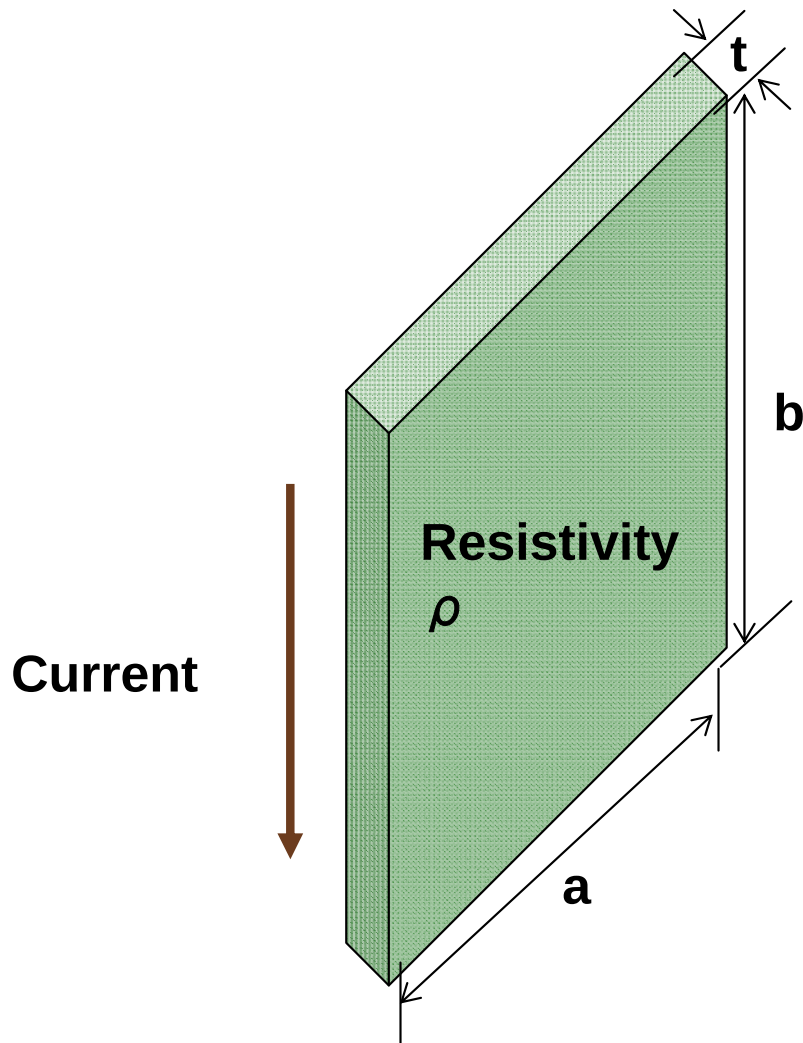
Sheet resistance

$$R_s = \frac{\rho}{t}$$

[Ω /square]

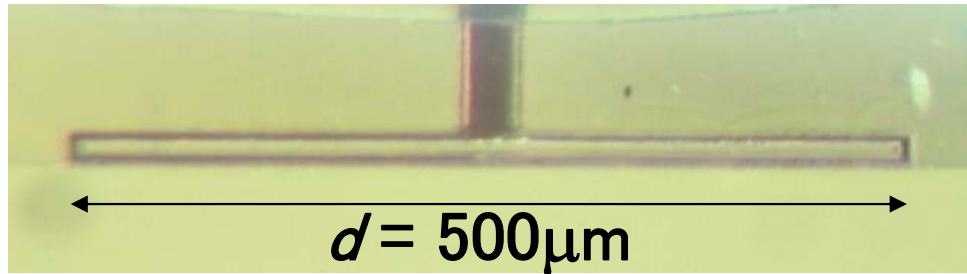
ρ : Resistivity

t : Film thickness



S. Ohnuma et al: Intermag2005

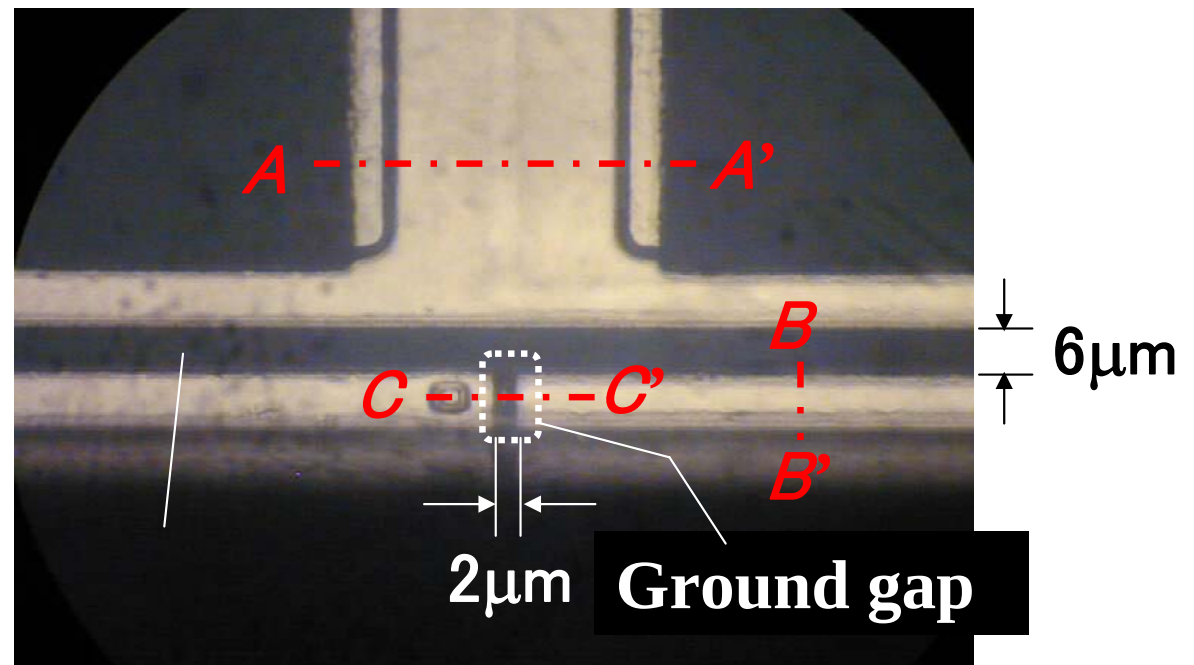
Thin-film shielded-loop coil



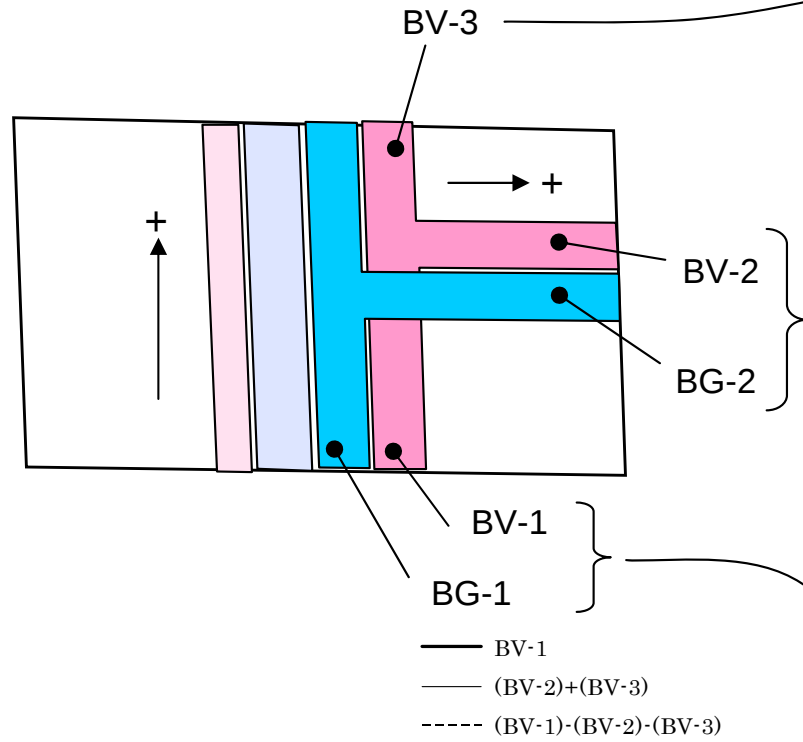
$d = 50, 100, 200, 500\mu\text{m}$

Lead portion

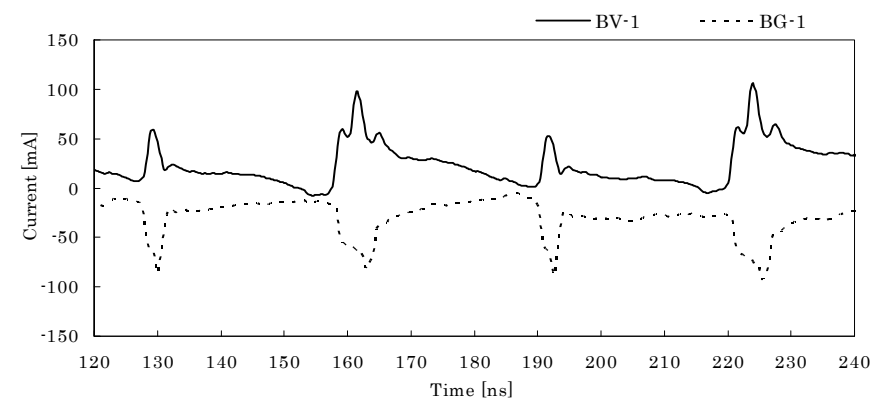
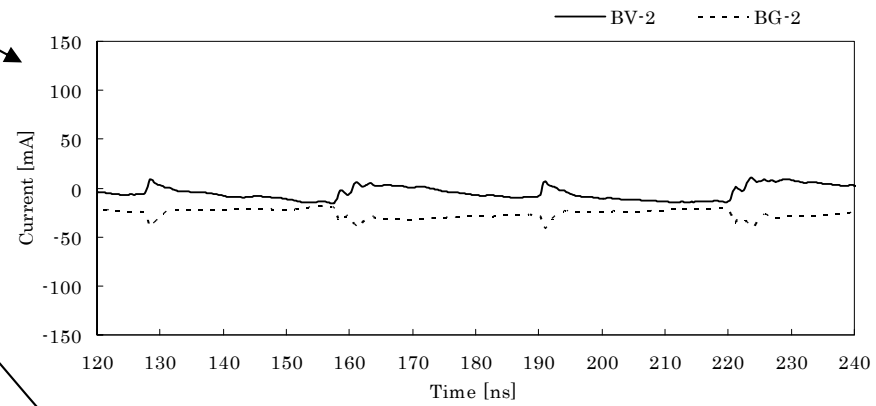
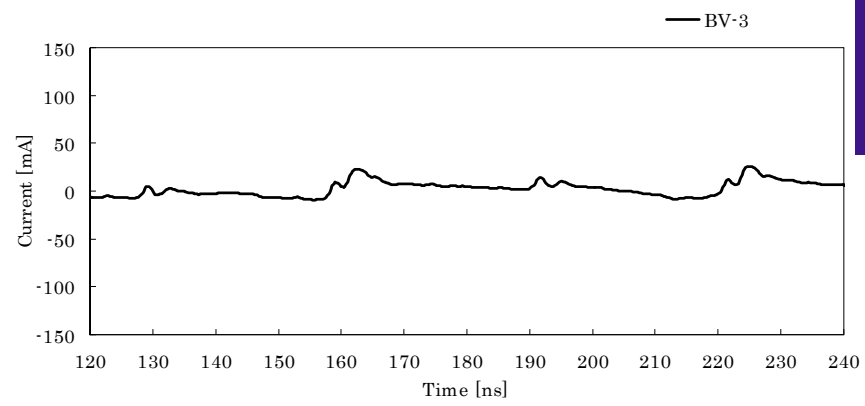
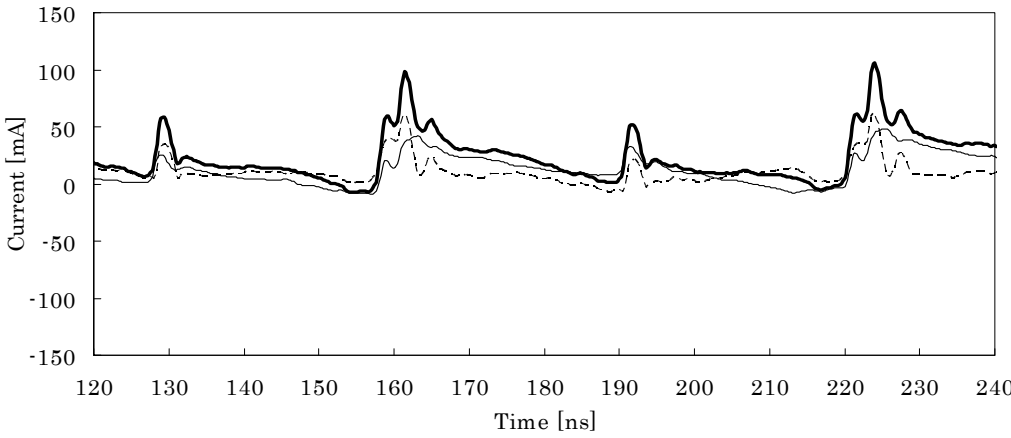
Loop portion



Time domain analysis



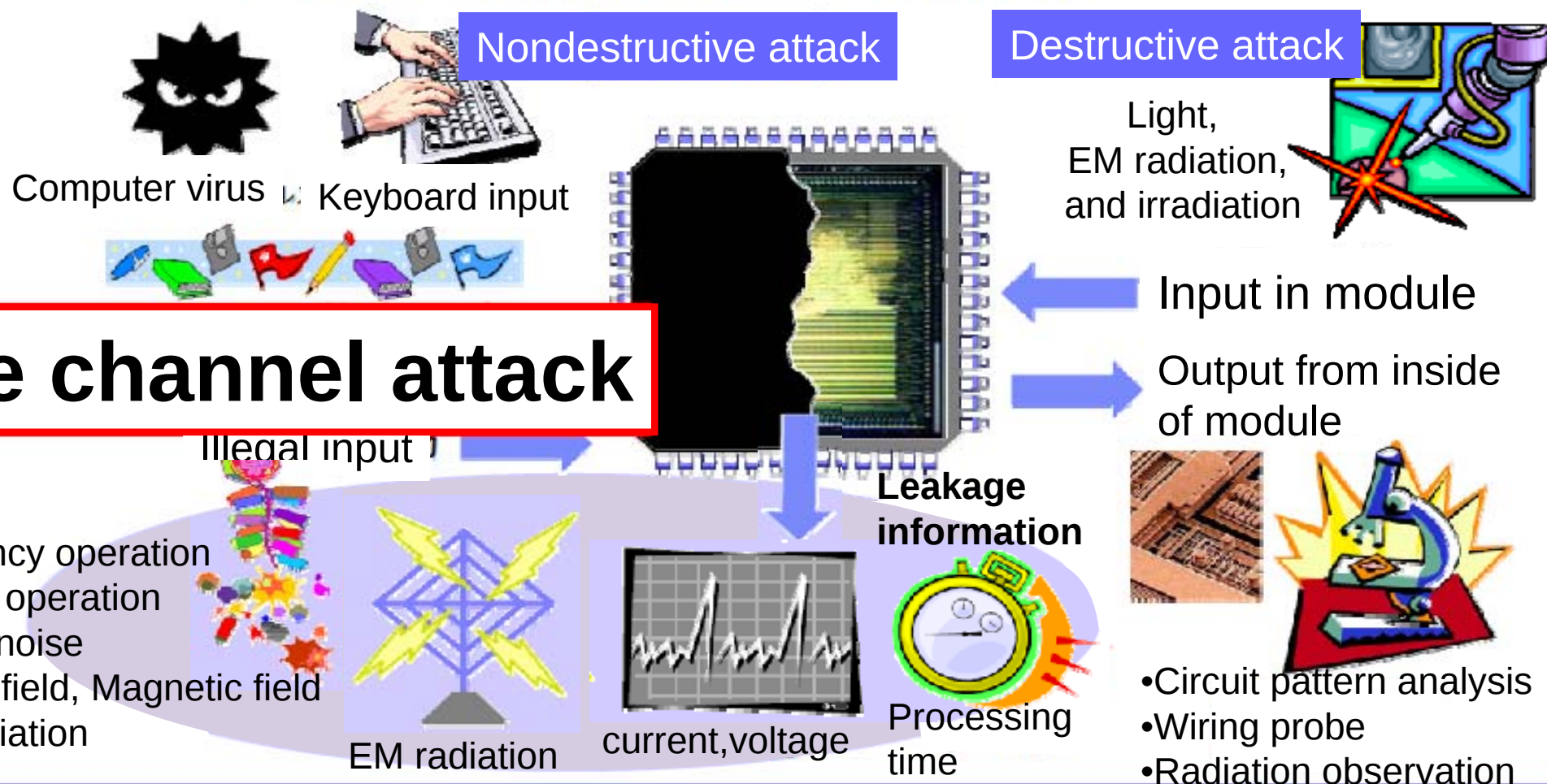
— BV-1
— (BV-2)+(BV-3)
- - - (BV-1)-(BV-2)-(BV-3)



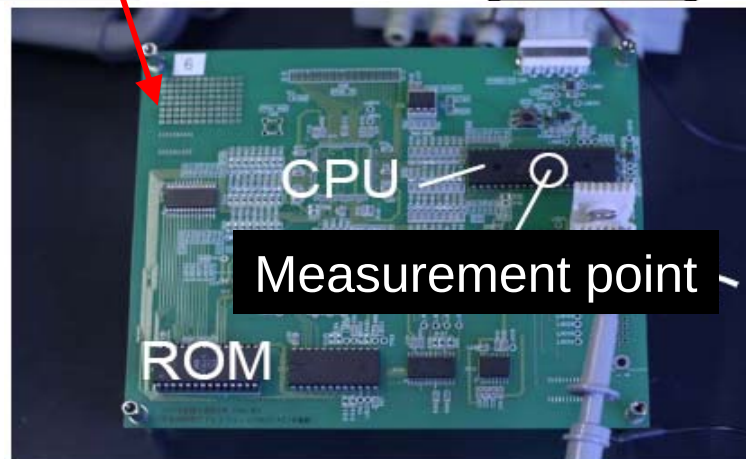
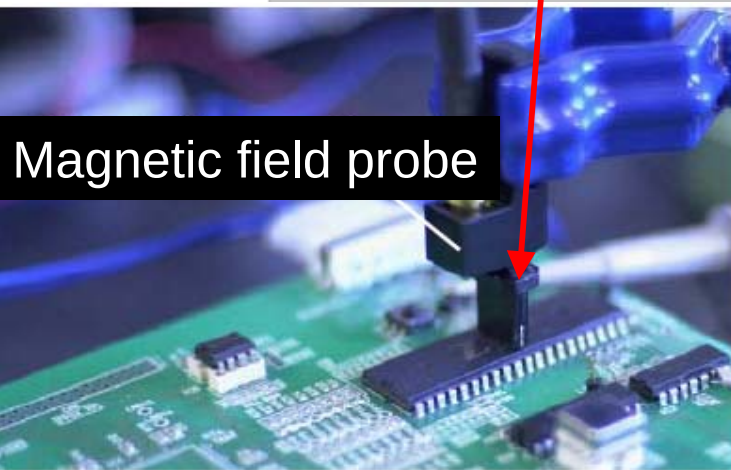
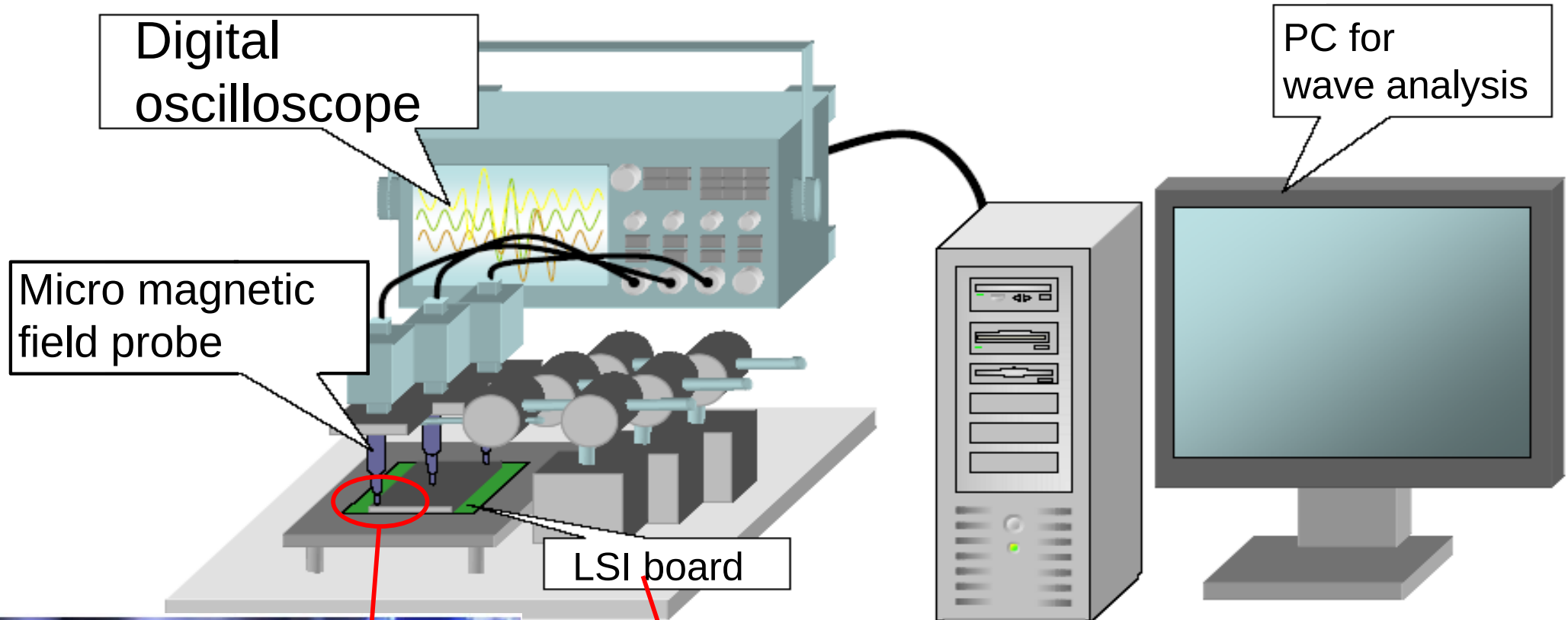
Side channel attack on cryptographic modules

A variety of side channel attack methods

- Analysis by combining various I/O to the module



Electromagnetic radiation analysis system that use micro magnetic field probe



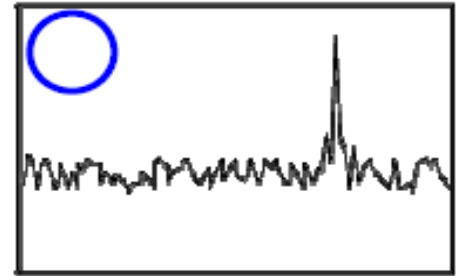
Differential Electromagnetic Analysis (DEMA)

Electromagnetic radiation from CPU depends changes of the data.

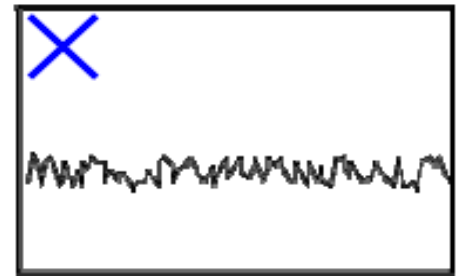
...DEMA is attack method that uses change in EM wave radiated from CPU while encryption.

Outline of DEMA

- I) Acquire wave form corresponding to various plaintexts (ciphertexts).
- II) Assume a part of the key.
- III) Assume 1 bit of internal variety from the key assumed.
- IV) Classify to two groups according to an internal variable is 0 or 1.
- V) Calculate difference between averages of the two groups.
- VI) Repeat II)-V) changing assumption of the key.
- VII) Consider the one with the maximum peak to be a correct key.



Assume the correct key



Assume the false key

Relation between sampling frequency and analytical accuracy

